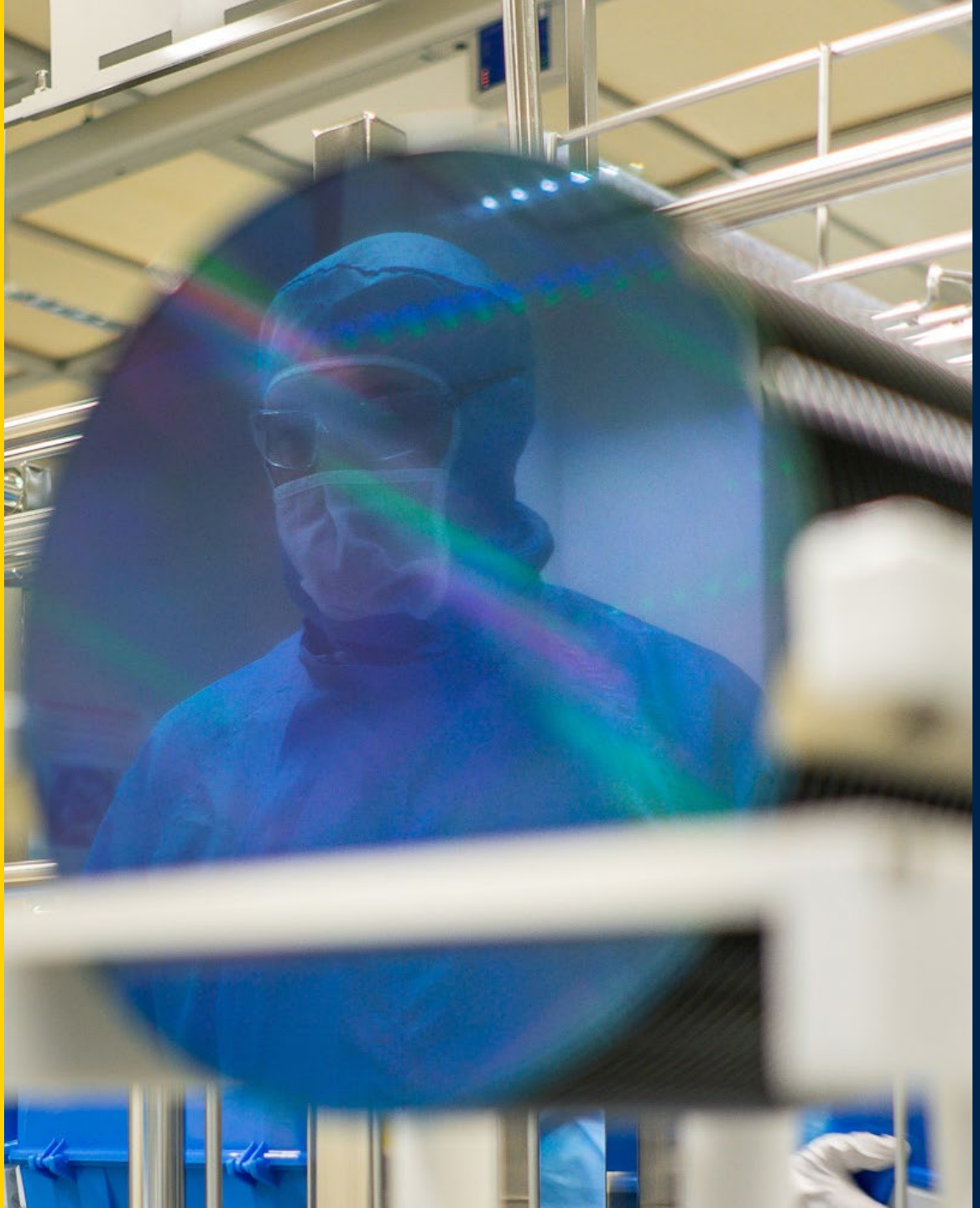


STMicroelectronics Investor presentation

July 2026

Forward looking information

Some of the statements contained in this document that are not historical facts are statements of future expectations and other forward-looking statements (within the meaning of Section 27A of the Securities Act of 1933 or Section 21E of the Securities Exchange Act of 1934, each as amended) that are based on management's current views and assumptions, and are conditioned upon and also involve known and unknown risks and uncertainties that could cause actual results, performance or events to differ materially from those anticipated by such statements due to, among other factors:

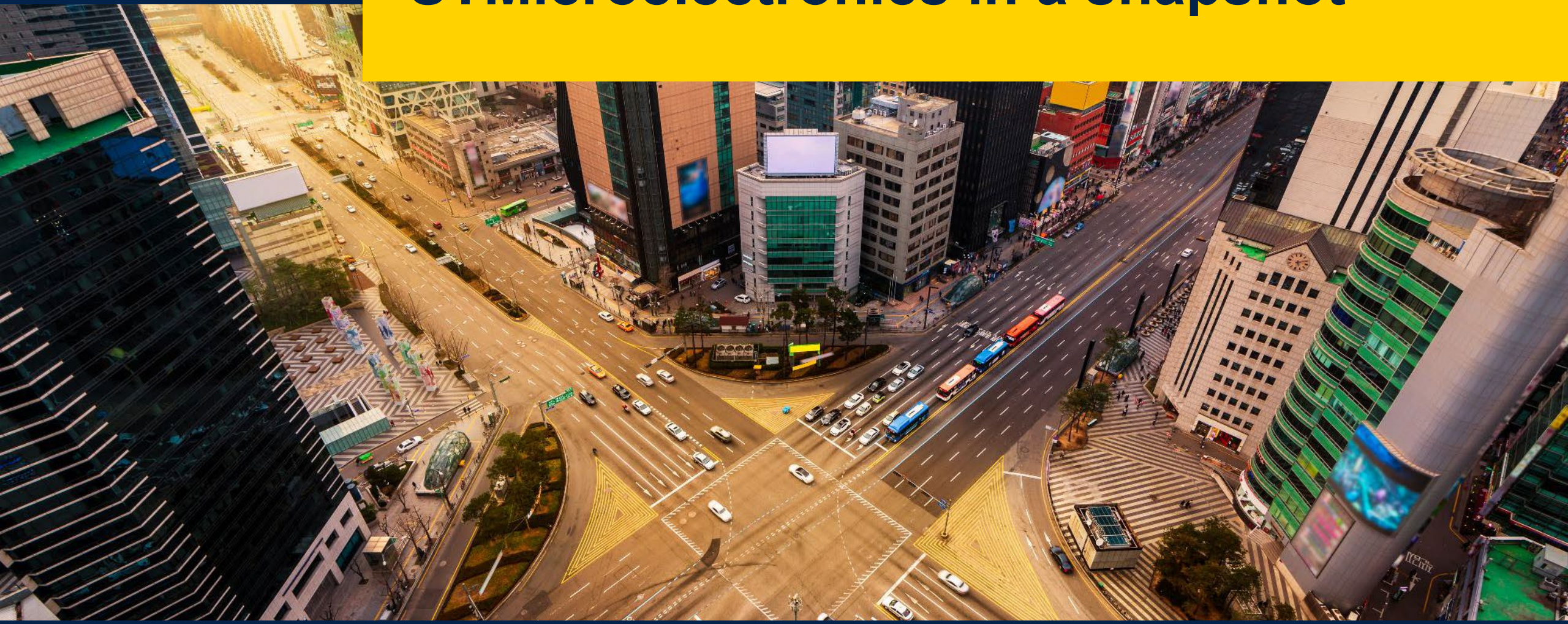
• changes in global trade policies, including the continuation, adoption and expansion of tariffs and trade barriers and sanctions, that are affecting and could further affect the macro-economic environment and are adversely impacting and could further adversely impact the demand for our products;
• uncertain macro-economic and industry trends (such as inflation and fluctuations in supply chains), which are impacting and may further impact production capacity and end-market demand for our products;
• customer demand that differs from projections, which may require us to undertake transformation measures that may not be successful in realizing the expected benefits in full or at all;
• the ability to design, manufacture and sell innovative products in a rapidly changing technological environment;
• changes in economic, social, public health, labor, political, or infrastructure conditions in the locations where we, our customers, or our suppliers operate, including as a result of macro-economic or regional events, geopolitical and military conflicts, social unrest, labor actions, or terrorist activities;
• unanticipated events or circumstances, which may impact our ability to execute our plans and/or meet the objectives of our research and development ("R&D") and manufacturing programs, which benefit from public funding;
• financial difficulties with any of our major distributors or significant curtailment of purchases by key customers;
• the loading, product mix, and manufacturing performance of our production facilities and/or our required volume to fulfill capacity reserved with suppliers or third-party manufacturing providers;
• availability and costs of equipment, raw materials, utilities, third-party manufacturing services and technology, or other supplies required by our operations (including increasing costs resulting from inflation);
• the functionalities and performance of our IT systems, which are subject to cybersecurity threats and which support our critical operational activities including manufacturing, finance and sales, and any breaches of our IT systems or those of our customers, suppliers, partners and providers of third-party licensed technology;
• theft, loss, or misuse of personal data about our employees, customers, or other third parties, and breaches of data privacy legislation;
• the impact of intellectual property ("IP") claims by our competitors or other third parties, and our ability to obtain required licenses on reasonable terms and conditions;
• changes in our overall tax position as a result of changes in tax rules, new or revised legislation, the outcome of tax audits or changes in international tax treaties which may impact our results of operations as well as our ability to accurately estimate tax credits, benefits, deductions and provisions and to realize deferred tax assets;
• variations in the foreign exchange markets and, more particularly, the U.S. dollar exchange rate as compared to the Euro and the other major currencies we use for our operations;
• the outcome of ongoing litigation as well as the impact of any new litigation to which we may become a defendant;
• product liability or warranty claims, claims based on epidemic or delivery failure, or other claims relating to our products, or recalls by our customers for products containing our parts;
• natural events such as severe weather, earthquakes, tsunamis, volcano eruptions or other acts of nature, the effects of climate change, health risks and epidemics or pandemics in locations where we, our customers or our suppliers operate;
• increased regulation and initiatives in our industry, including those concerning climate change and sustainability matters and our goal to become carbon neutral in all direct and indirect emissions (scopes 1 and 2), product transportation, business travel, and employee commuting emissions (our scope 3 focus), and to achieve our 100% renewable electricity sourcing goal by the end of 2027;
• epidemics or pandemics, which may negatively impact the global economy in a significant manner for an extended period of time, and could also materially adversely affect our business and operating results;
• industry changes resulting from vertical and horizontal consolidation among our suppliers, competitors, and customers;
• the ability to successfully ramp up new programs that could be impacted by factors beyond our control, including the availability of critical third-party components and performance of subcontractors in line with our expectations; and
• individual customer use of certain products, which may differ from the anticipated uses of such products and result in differences in performance, including energy consumption, may lead to a failure to achieve our disclosed emission-reduction goals, adverse legal action or additional research costs.

Such forward-looking statements are subject to various risks and uncertainties, which may cause actual results and performance of our business to differ materially and adversely from the forward-looking statements. Certain forward-looking statements can be identified by the use of forward-looking terminology, such as "believes", "expects", "may", "are expected to", "should", "would be", "seeks" or "anticipates" or similar expressions or the negative thereof or other variations thereof or comparable terminology, or by discussions of strategy, plans or intentions.

Some of these risk factors are set forth and are discussed in more detail in "Item 3. Key Information — Risk Factors" included in our Annual Report on Form 20-F for the year ended December 31, 2025 as filed with the Securities and Exchange Commission ("SEC") on February 26, 2026. Should one or more of these risks or uncertainties materialize, or should underlying assumptions prove incorrect, actual results may vary materially from those described in this document as anticipated, believed or expected. We do not intend, and do not assume any obligation, to update any industry information or forward-looking statements set forth in document to reflect subsequent events or circumstances.

Unfavorable changes in the above or other factors listed under "Item 3. Key Information — Risk Factors" from time to time in our SEC filings, could have a material adverse effect on our business and/or financial condition.

STMicroelectronics in a snapshot



We are creators and makers of technology



One of the world's largest semiconductor companies

~49,000 employees
of which **~9,500** in R&D

$11.8 billion revenues
in 2025

Over **80** sales & marketing offices serving over **200,000** customers across the globe

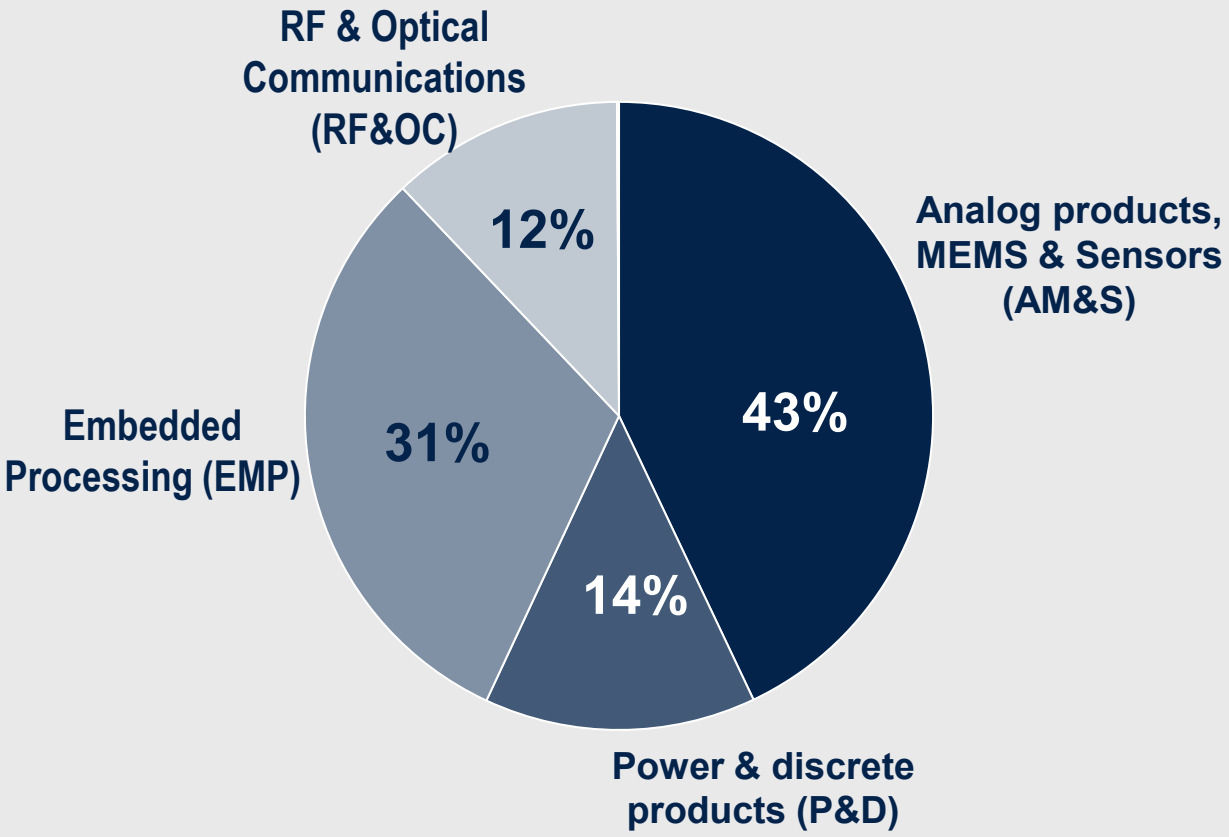
14 main manufacturing sites

Signatory of the United Nations Global Compact (UNGC)
Member of the Responsible Business Alliance (RBA)

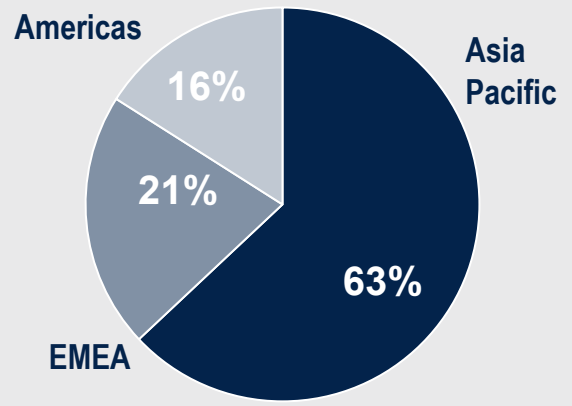
As of December 31, 2025

FY 2025 revenues overview

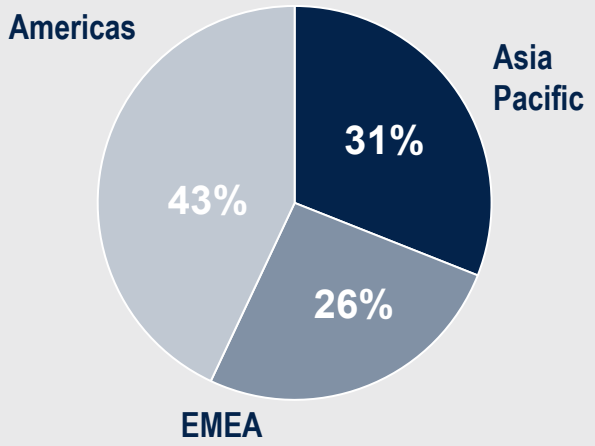
% by reportable segments



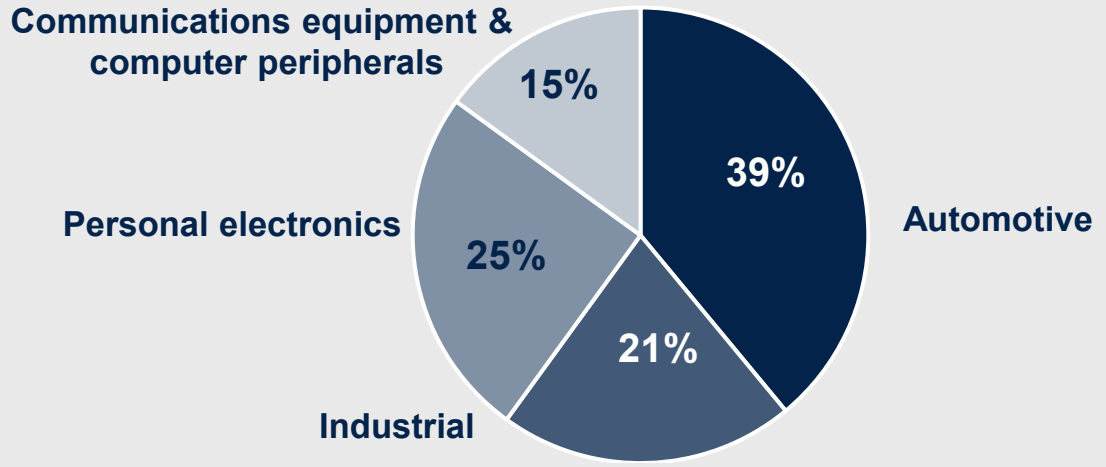
% by shipment location



% by region of origin



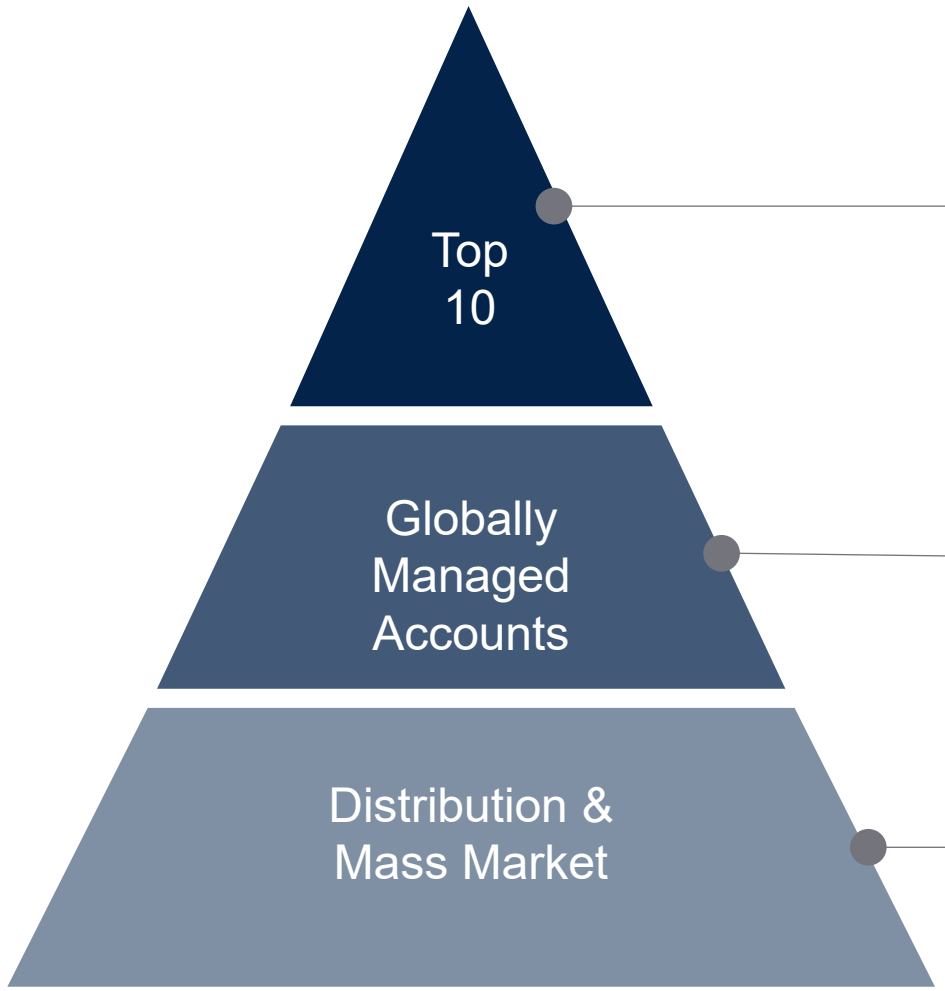
% by end market



We serve more than 200,000 customers

47% of revenues

53% of revenues



Top 10 Customers* 2025

Apple	Mobileye
Bosch	Samsung
Continental	SpaceX
Denso	Tesla
HP	Vitesco

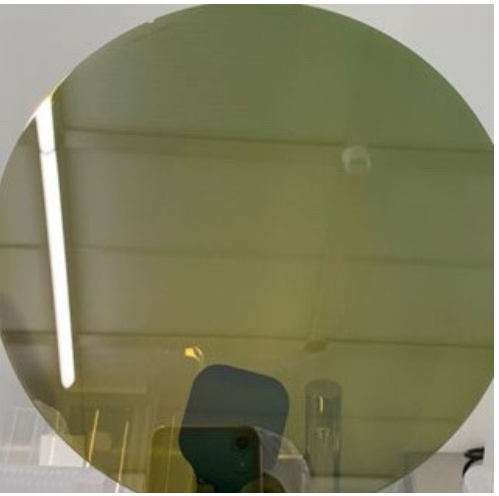
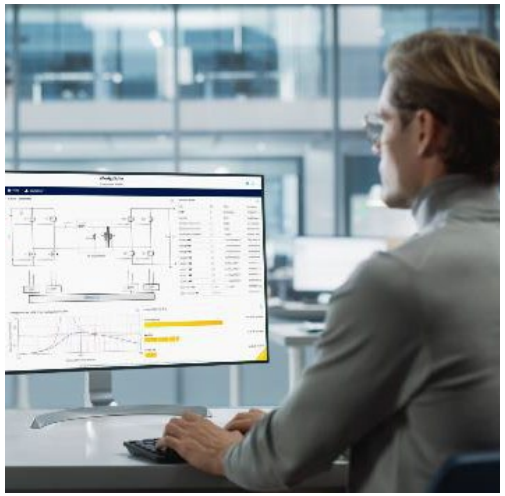
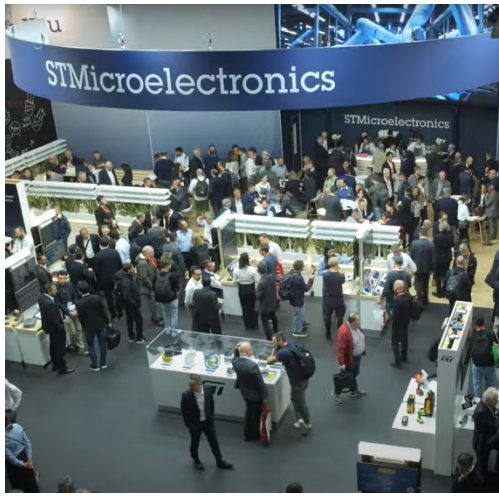
Unified worldwide account management tailored to each account to provide global coverage and service

Standard process, reporting & follow-up in Sales & Marketing worldwide

Differentiated approach by type of customer

*In alphabetical order

IDM model providing strong competitive advantage and supply chain resilience for our customers

Process development and qualification	Chip design	Wafer fabrication	Assembly & test	Sales & support
				

Full control and optimization of the value chain

ST technology and manufacturing strategy is a key business enabler

In-house manufacturing complemented by partnerships

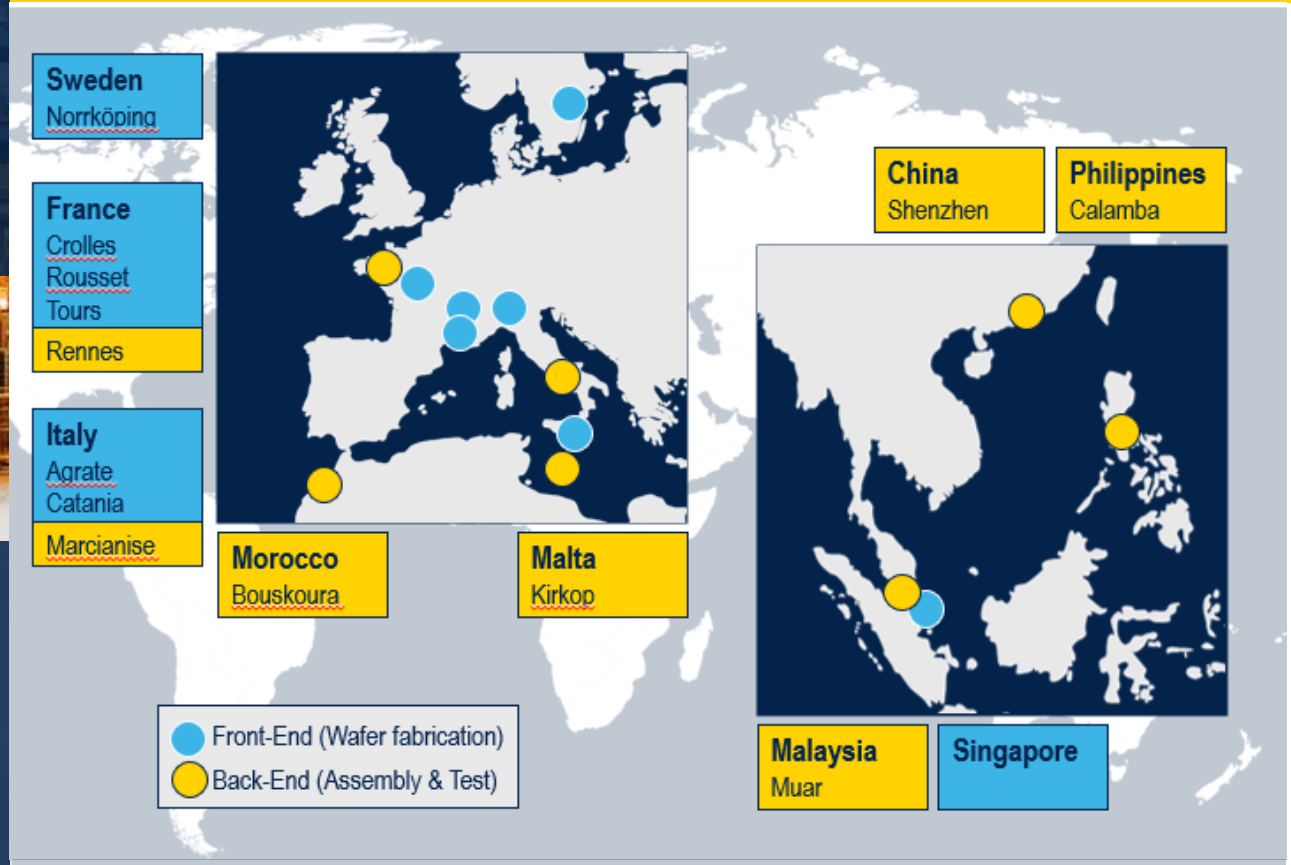
- Agile and competitive footprint
- Reliable supply chain for our customers
- Product differentiation through proprietary technologies



Manufacturing roadmap

- Accelerating silicon capacity transition from 200 mm to 300 mm
- Test consolidation in two hubs
- Silicon Carbide – transition to 200 mm in Catania with fully vertically integrated operations and JV in China
- China-for-China supply chain

ST in-house manufacturing



China-for-China operating model to support domestic China growth

Operate locally to support fast-changing and highly-competitive China market

Fully localized, scalable integrated device manufacturing

Front-end manufacturing for Silicon Carbide with ST-Sanan JV

Captive capacity corridor in partnership with HHGrace on 40 nm, OFT, BCD/IGBT

GaN technology development and manufacturing agreement with Innoscience

Back-end manufacturing extended Shenzhen Campus (Manufacturing assembly & test, R&D assembly & test, world-class failure analysis and reliability labs).

Application center in Shanghai

OFT: Oxide Filled Trench

Cost-effective & resilient supply chain

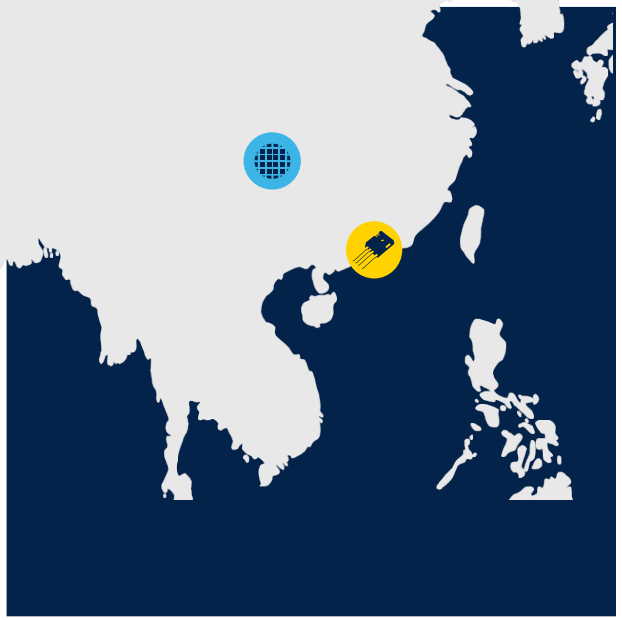
Selective use of local equipment vendors, predominant use of local materials vendors to minimize possible geopolitical constraints

Shenzhen

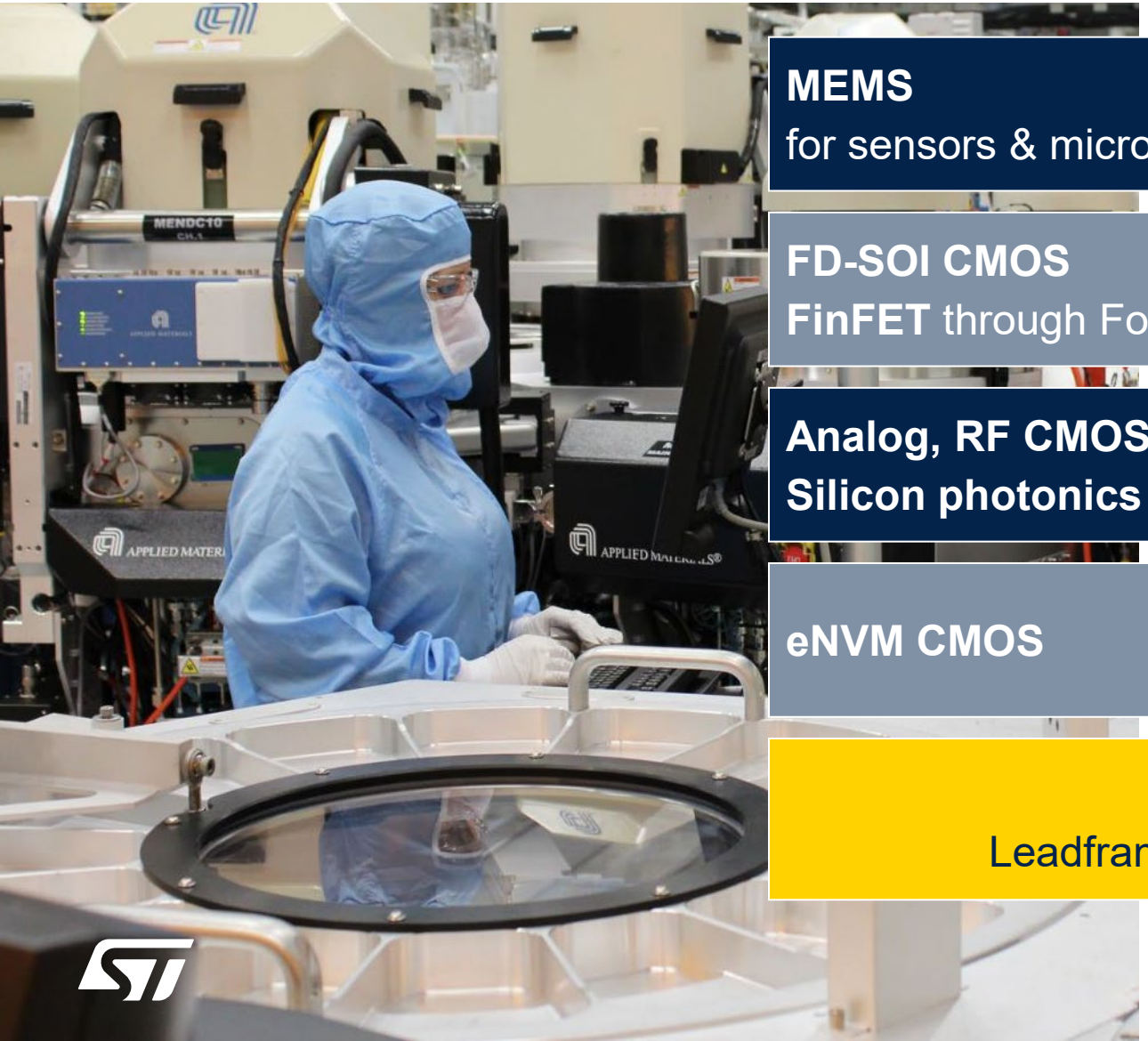
Back-end assembly & test

Chongqing

SiC Front-end manufacturing



Differentiated technologies are our foundation



MEMS
for sensors & micro-actuators

Smart Power: BCD
(Bipolar - CMOS - Power DMOS)

FD-SOI CMOS
FinFET through Foundry

Discrete, Power MOSFET, IGBT
Silicon Carbide, Gallium Nitride

Analog, RF CMOS & BiCMOS,
Silicon photonics

Vertical Intelligent Power

eNVM CMOS

Optical sensing solutions

Packaging technologies
Leadframe – Laminate – Sensor module – wafer level

Our strategy stems from key long-term enablers

Smart Mobility



Helping car manufacturers make driving safer, greener, and more connected for everyone

Power & Energy



Enabling industries to increase energy efficiency everywhere and the use of renewable energy

Cloud-connected Autonomous Things



Supporting the proliferation of secure, connected, autonomous devices enabled by edge AI

We will be carbon neutral by our 40th anniversary

Milestones

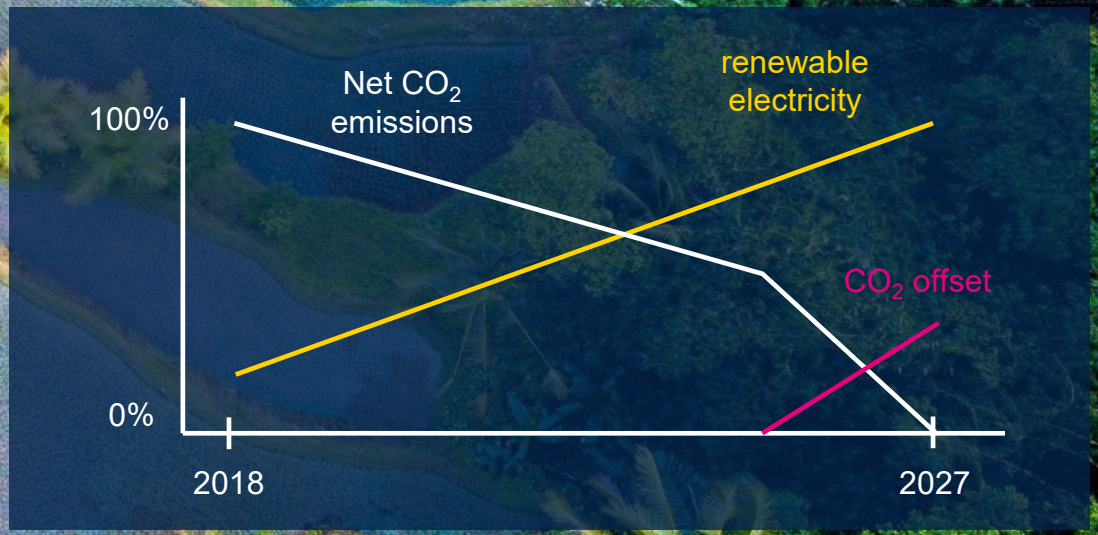
Carbon neutral by 2027 (on Scope 1 & 2 and focusing on product transportation, business travel and employee commuting emissions for scope 3)

Sourcing **100% renewable electricity** by 2027

Collaborative programs and partnerships for carbon neutrality in our ecosystems

In 2025, we achieved two strategic milestones endorsed by the Science Based Targets initiative (SBTi):

- 50% reduction of Scope 1 and 2 GHG emissions versus 2018
- 80% renewable electricity adoption with ST going further by sourcing 86% renewable electricity in 2025



Our value proposition for all our stakeholders

For our **shareholders**



Return value in line with our objective

Sustainable and profitable growth

For our **customers**



Provide differentiating enablers

Independent, reliable & secure supply chain

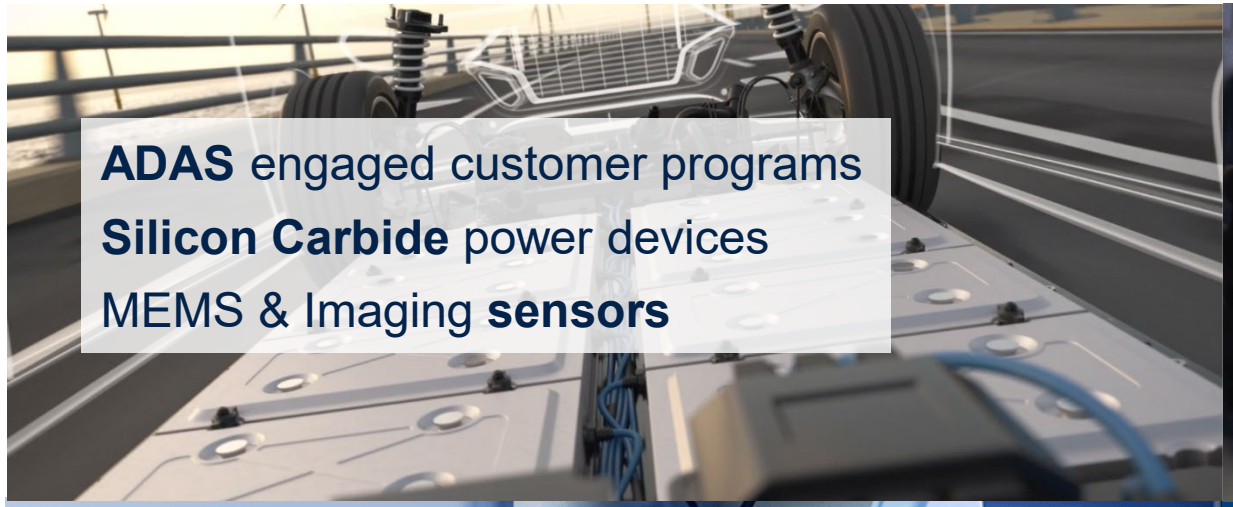
For all our **stakeholders**



Committed to sustainability

Our values: Integrity – People – Excellence

Company-specific revenues growth drivers including



ADAS engaged customer programs

Silicon Carbide power devices

MEMS & Imaging **sensors**

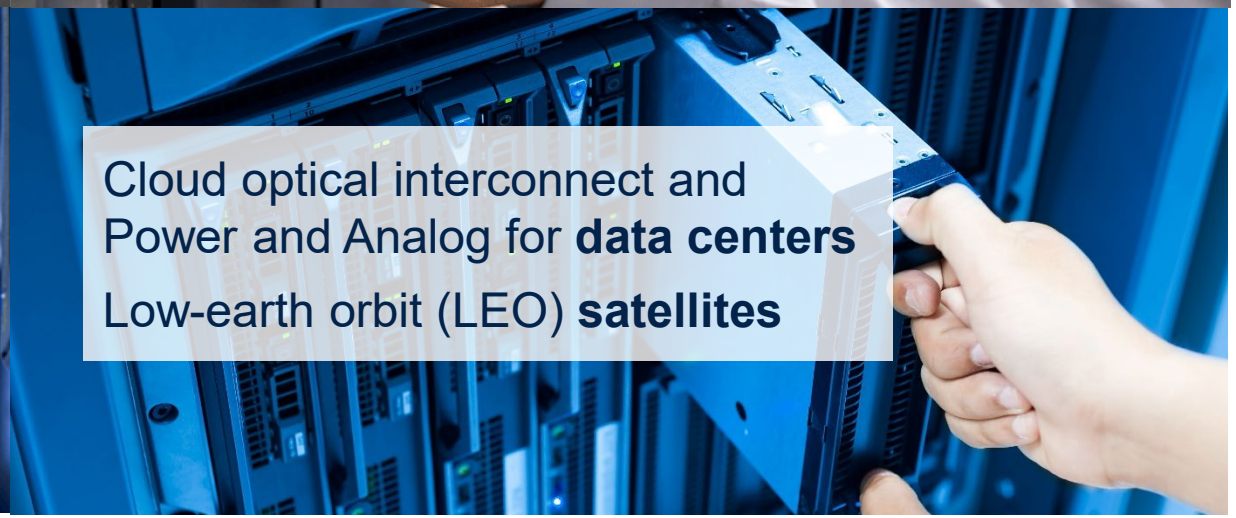


Engaged customer programs in **sensors & analog**



General purpose **microcontrollers**

Humanoid robots

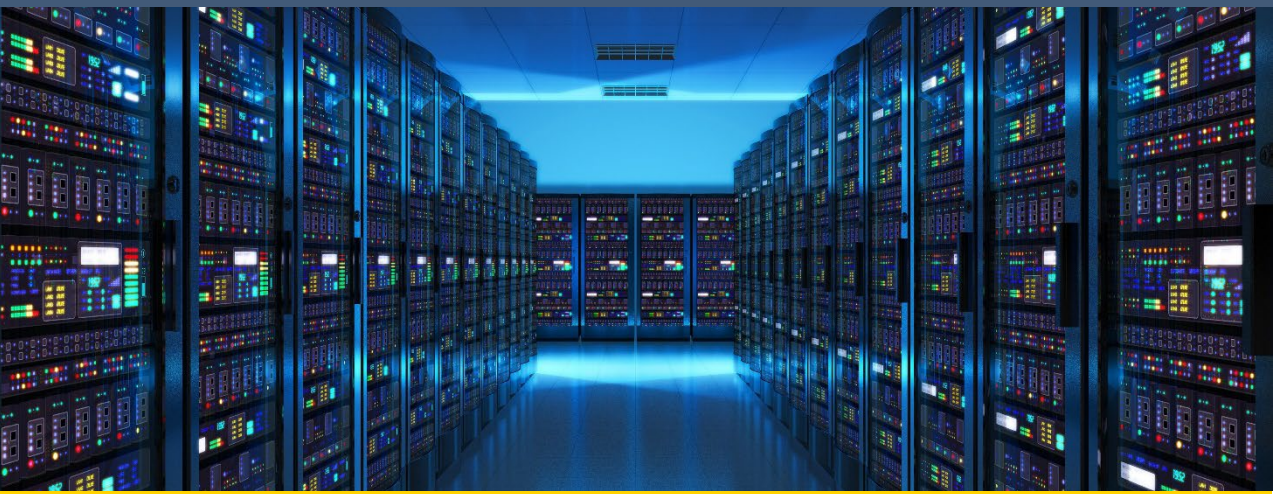


Cloud optical interconnect and Power and Analog for **data centers**

Low-earth orbit (LEO) **satellites**

Entering the Cloud and physical AI era

Cloud AI: ~400 products addressing AI Data Centers



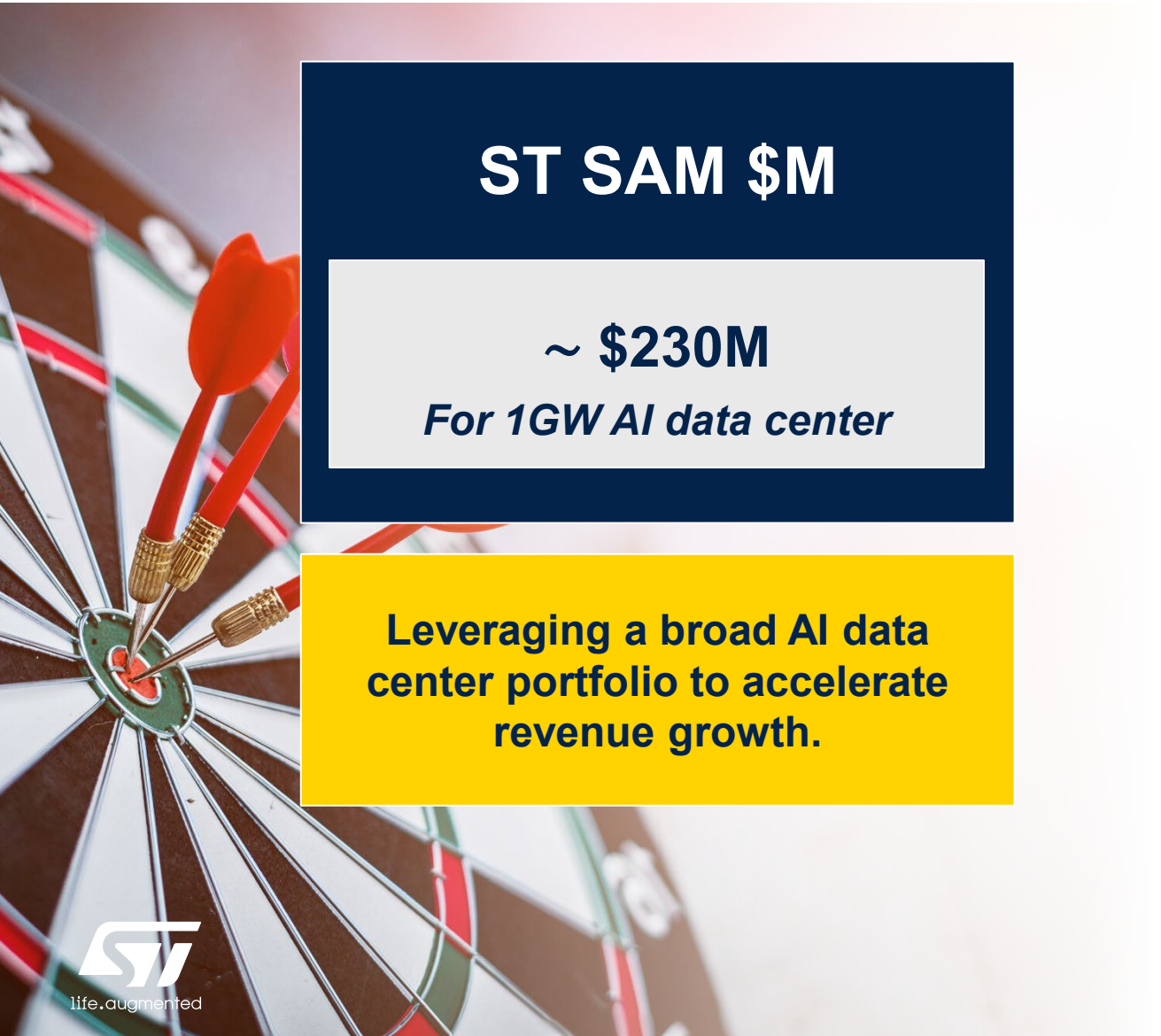
- ST optical technologies critical for AI infrastructure
- ST has the power technologies for next-generation AI data centers

Physical AI: 500+ ST components in humanoid robots



- ST is ideally positioned to win in the growing sensor market driven by physical AI
- ST is strategic enabler for humanoids robots leveraging its broad portfolio

ST SAM Content per 1 GW AI data center



ST SAM $M

~ $230M

For 1GW AI data center

Leveraging a broad AI data center portfolio to accelerate revenue growth.

IT Rack
with PSU



IT Rack
+ Side-car



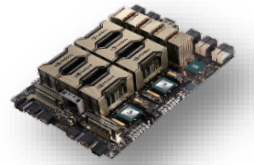


OPTICAL
Transceiver with fibers

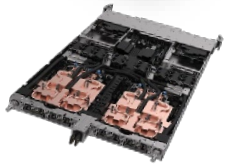


PSU
Power the full rack

HVDC
Power the server



DC DC
Power the GPUs



Compute tray
Board controller

Source: Arete, LightCounting, NVIDIA, ST estimates

life.augmented

Continued strong demand in AI datacenters, reflecting the success of our product and technology portfolio



Driven by continued strong demand in AI datacenters, **we are raising our revenue ambition for datacenters**

Data center revenues are now expected **above $1 billion in 2026**

Assuming the current dynamic continues and with the current engagements we have, Data center revenues are now expected **well above $2 billion in 2026**

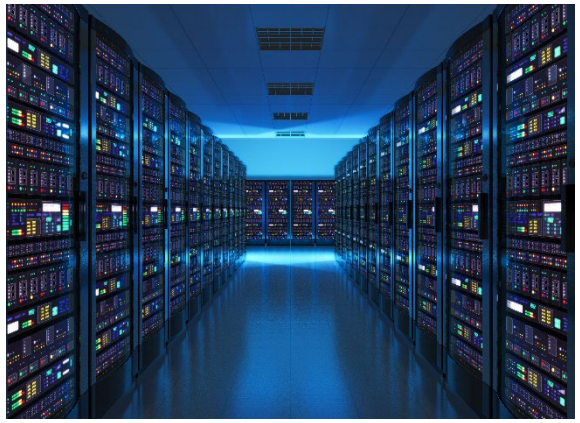
Strategic collaboration with AWS

Multi-year, multi-billion $ commercial engagement with AWS serving several product categories

A major milestone to position ST in the AI revolution.

This collaboration establishes ST as a strategic supplier of advanced semiconductor technologies and products that AWS integrates into its compute infrastructure.

ST will supply specialized capabilities across high-bandwidth connectivity, including high-performance mixed-signal processing, advanced MCUs for intelligent infrastructure management, and analog and power ICs.





~$600 current addressable BoM in humanoid robots
Sensors are core components

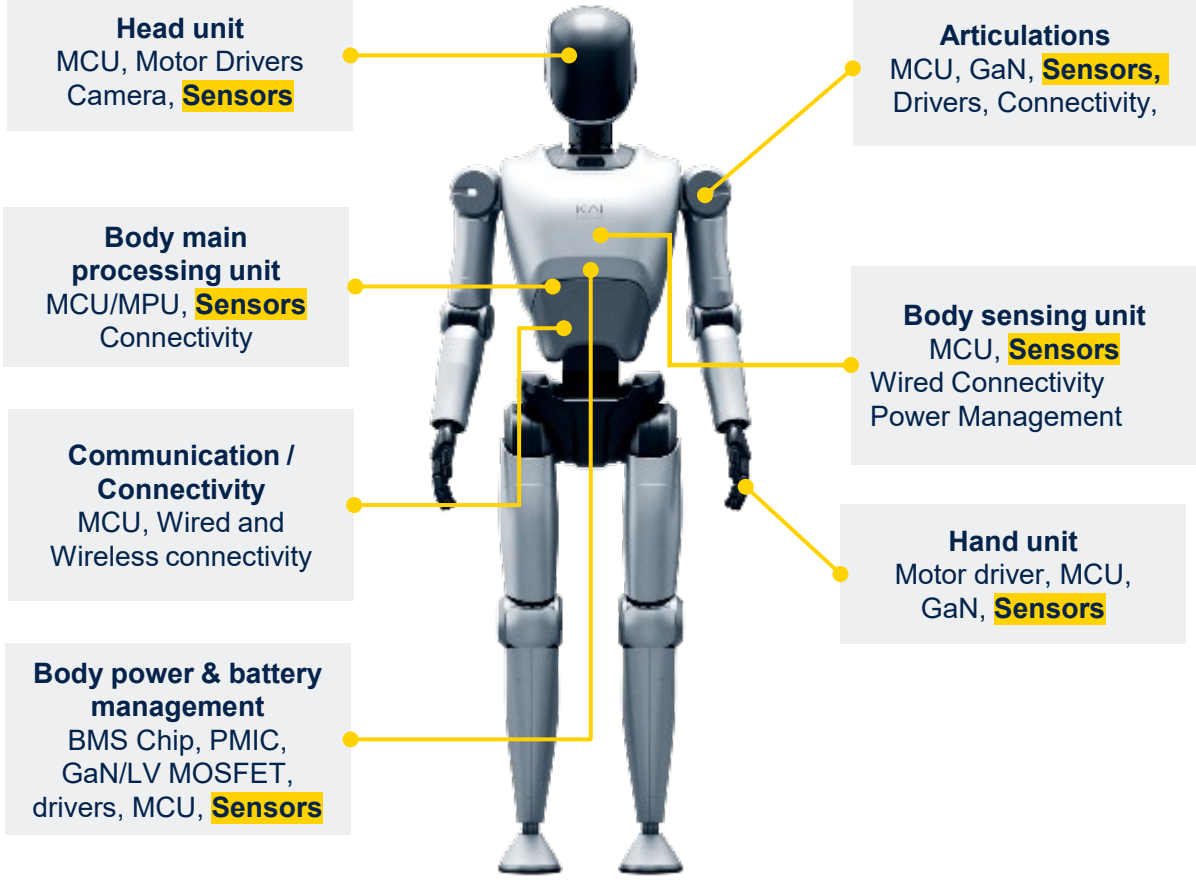
Sensors are core components enabling further ST component attach

Opportunity addressed at system architecture level leveraging our wide portfolio

Engagements with major OEMS in US, Europe China and APeC

Deep integration into the value chain

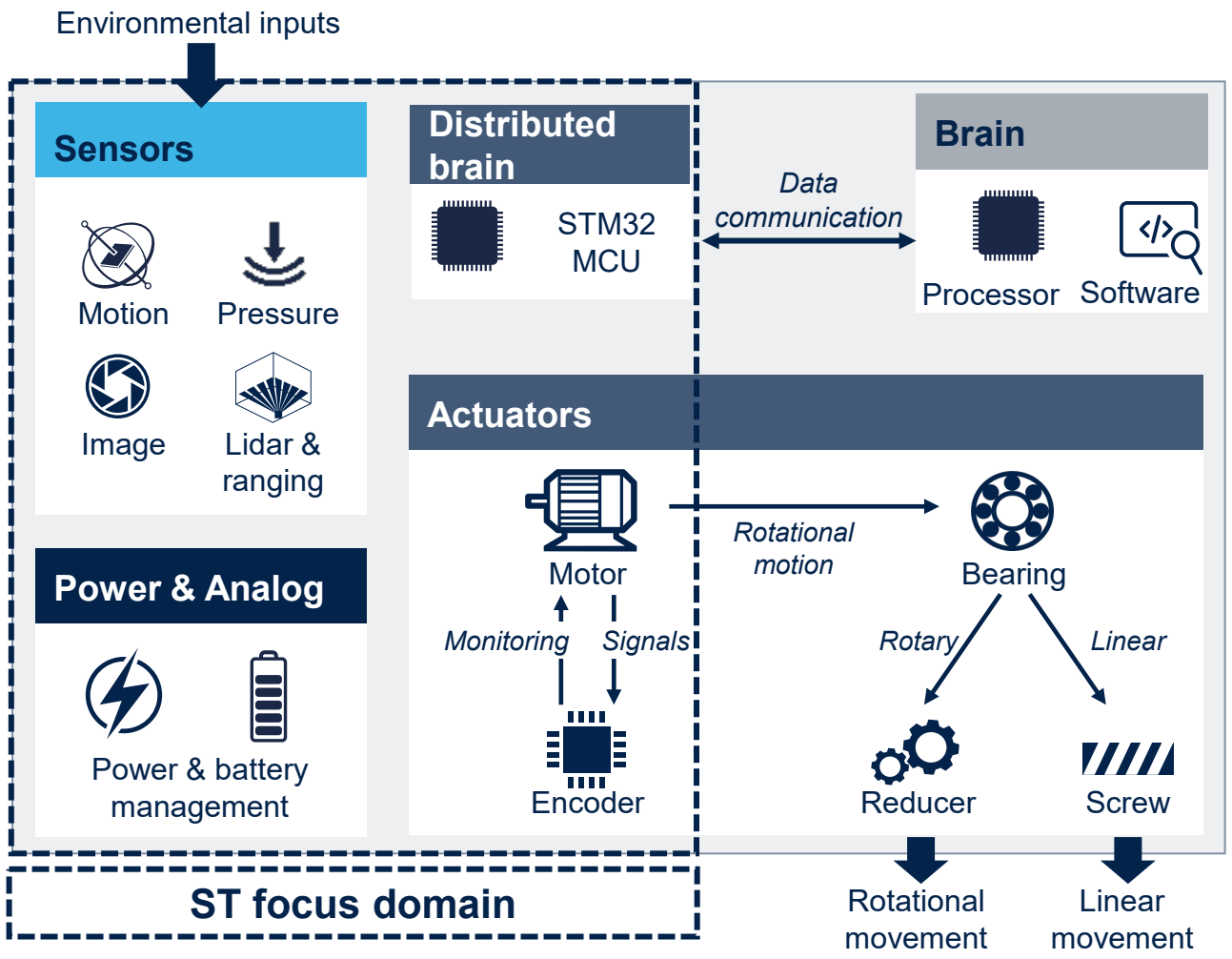
Sensors are present in most units of the humanoid robot



ST is uniquely positioned to address humanoid robots through its broad portfolio



Flow diagram



Main blocks

- Brain: main CPU / GPU
- **Distributed brain: MCU**
- **Energy**
  - Power control
  - Battery management
- **Communication**
  - In robot network
  - Wireless communication
  - Human machine interface
- **Sensors**
- **Muscles / joints / movements**
  - Motor driver modules

ST and SpaceX: Connecting the unconnected

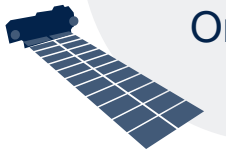
10 years of co-designing products for user terminals and satellites, building Starlink global broadband network



ST's opportunity in the fast growing LEO Broadband market

2025	2028	2030
LEO credibility & viability proven by Starlink	More constellations being deployed, including D2C	China constellation deployment
Understanding of LEO strategic importance	Developments for strategic independence	LEO Satellite part of global connectivity systems
New constellations being deployed	Connectivity to the unconnected	Further boost in developing countries
~9M active customers at Starlink	**>100M** cumulative User Terminal deployed	**>200M** cumulative User Terminal deployed
ST SAM* $650M	**ST SAM $2B**	**ST SAM $2.9B**
Starlink Kuiper OneWeb	Starlink Kuiper China OneWeb	Starlink Kuiper China TeraWave Lightspeed OneWeb / IRIS²







How ST wins and grows

BiCMOS competitiveness & high-volume **Panel Level Packaging**	**New BiCMOS generation** with increased performance for Ka and higher bands	Pervasion to **other constellations** Pervasion to **other geographies**

D2C: Direct-to-Cell

** ST SAM: LEO Broadband electronics excluding memories*

Source: ST analysis

ST’s Space business ambition



Well above $3 billion over the next 3 years ('26-’28)
Expected generated cumulative revenues given the current market trends

Remaining the leading semiconductor provider in New Space

STMicroelectronics
Q2 FY 2026 Financial Results



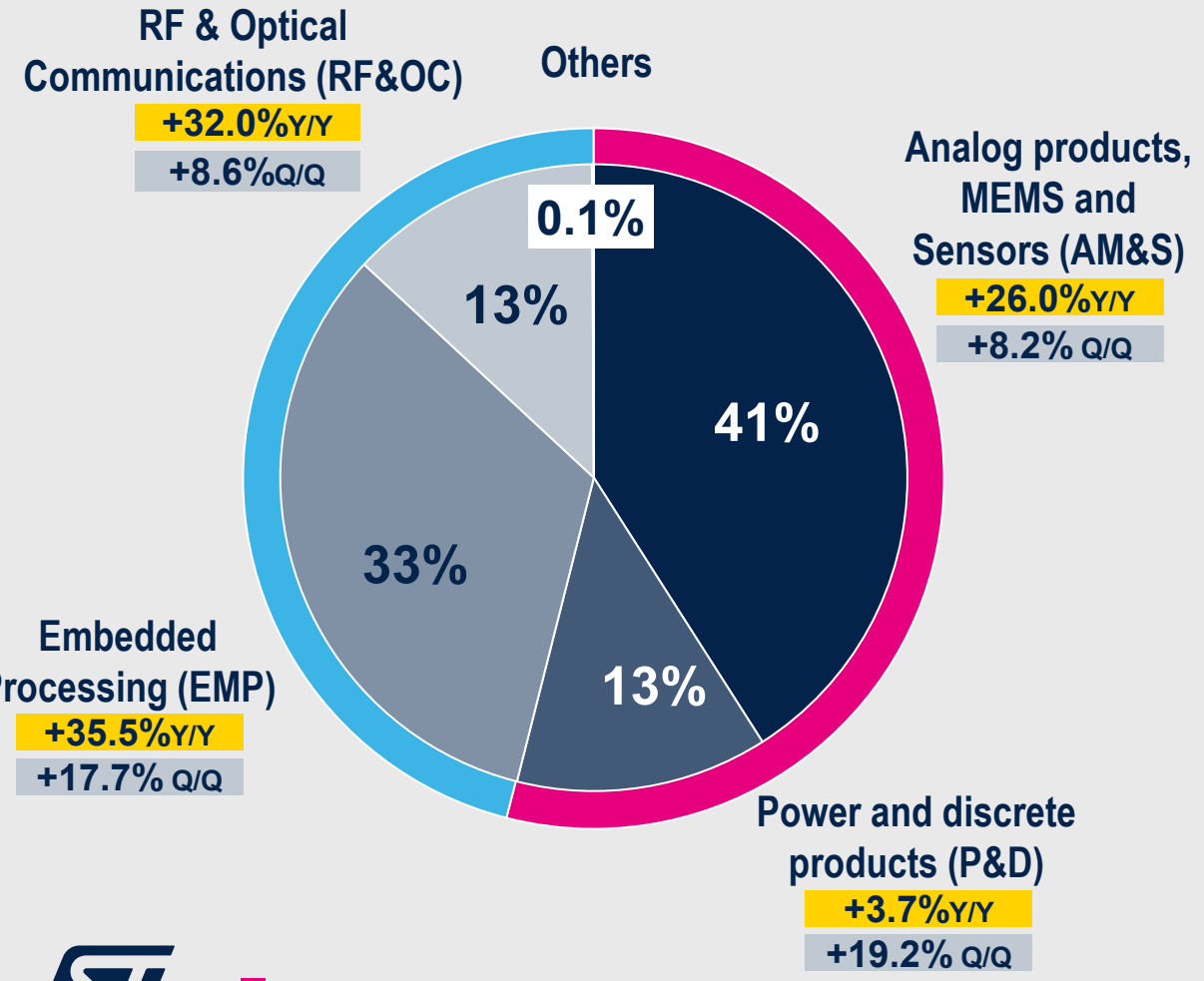
Highlights

Q2 2026	• Net revenues of $3.49B increased 26.0% Y/Y and 12.7% Q/Q. Revenues came above the mid-point of our business outlook range, driven by higher revenues in CECP and Automotive. • Gross margin was 34.8% and non-U.S. GAAP* gross margin was 35.2%; both in line with the mid-point of our business outlook range. • Operating margin was 5.4%, net income was $222M and EPS $0.24. On a Non-U.S. GAAP* basis, operating margin was 7.7%, net income was $291M and EPS $0.31.
	• During the quarter demand increased further, with strong bookings in all end markets. We saw improved visibility and signs of tight supply in several product categories. Inventory in distribution is now below our standard target.
Q3 2026	• Outlook at mid-point is for net revenues of $3.70B, increasing 16.2% Y/Y and 6.2% Q/Q. • Gross margin expected to be about 37.0% at the mid-point.
	• We anticipate a revenue growth acceleration in Q4, mainly driven by our engaged customer programs in AI datacenters and LEO satellite communication. We expect Q4 revenues above $4B, this translates into a H2 vs H1 growth above our normal 15% seasonality.
	• Driven by continued strong demand in AI datacenters, we are raising our revenue ambition for datacenters. Revenues are now expected above $1B in 2026 and, assuming the current dynamic continues and with the current engagements we have, well above $2B in 2027. This confirms ST's strong position in the evolving AI datacenters.

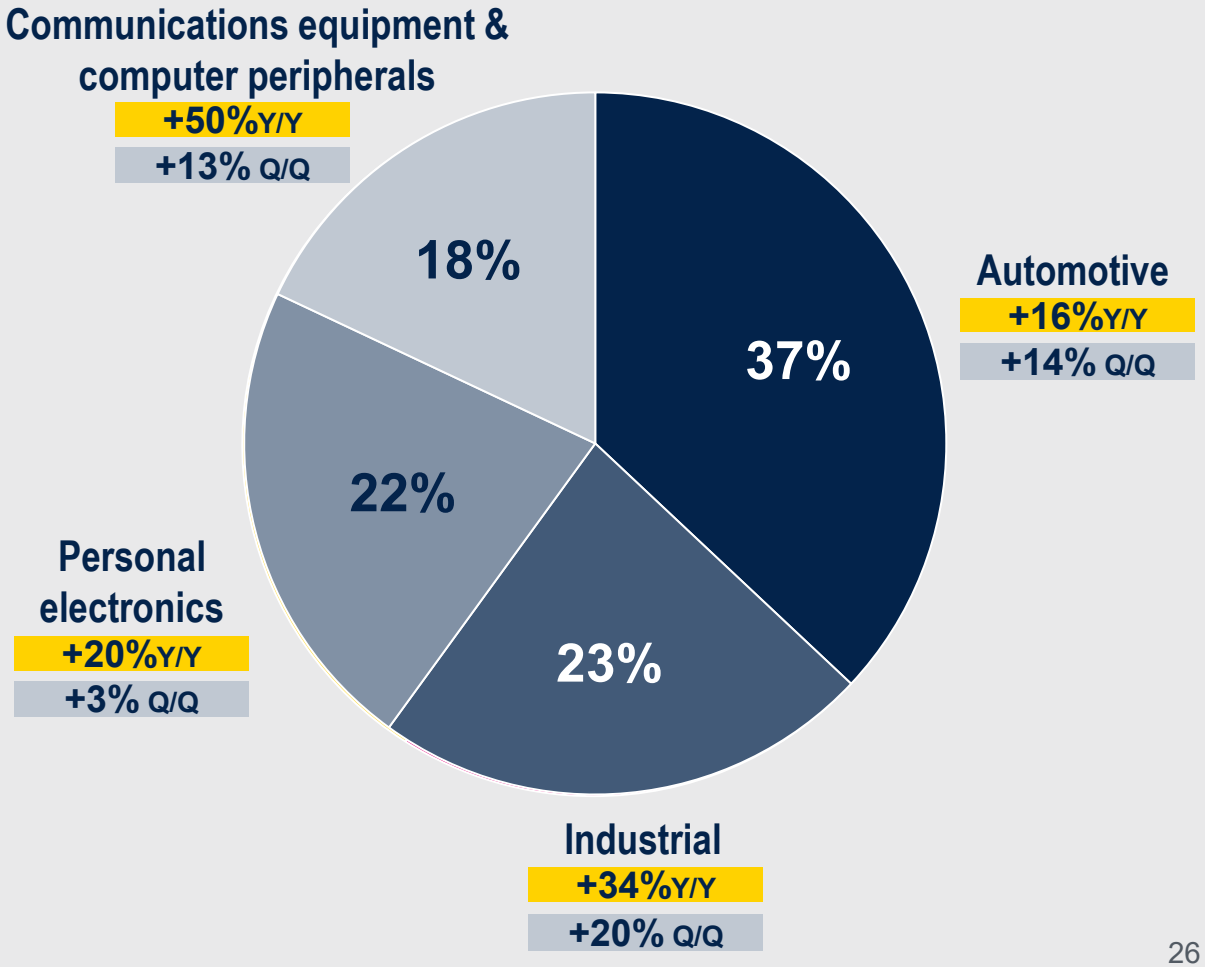
***Non-U.S. GAAP measure**. See Appendix for additional information explaining why the Company believes these measures are important.

Q2 2026 Revenues dynamic

% by reportable segments

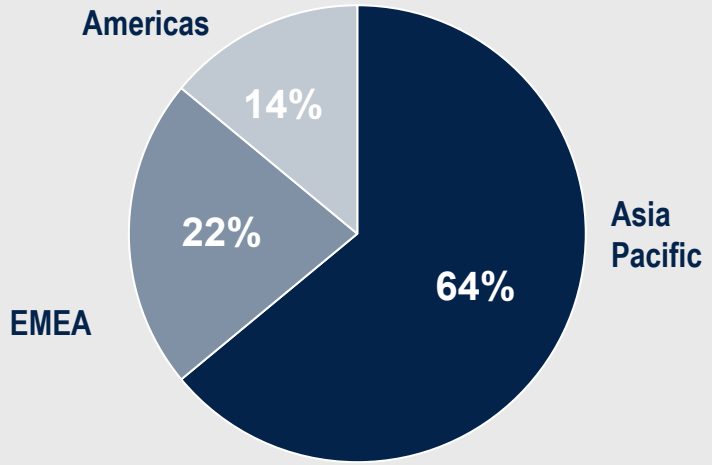


% by end market

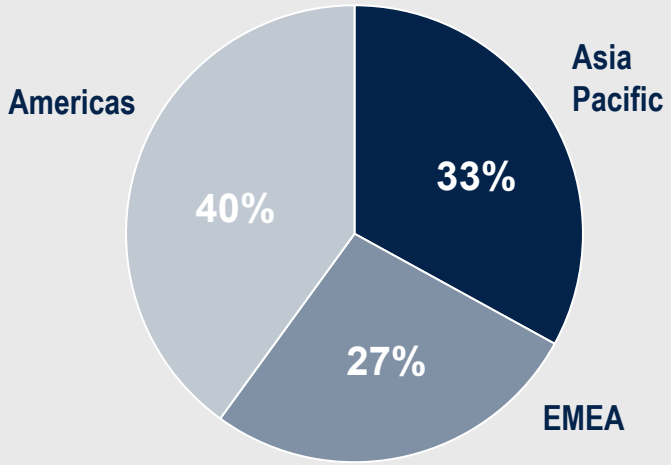


Q2 2026 Revenues

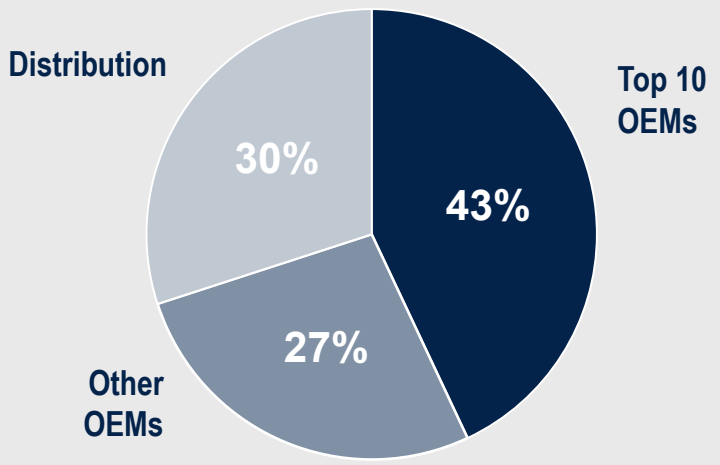
% by shipment location



% by region of origin

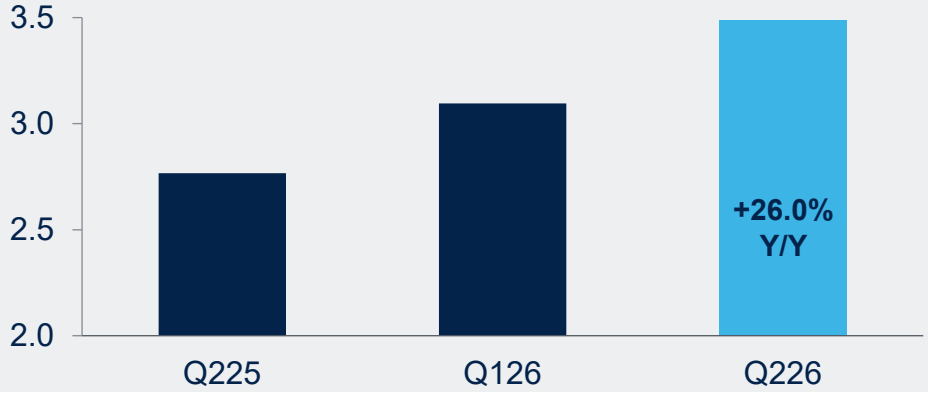


% by customer type

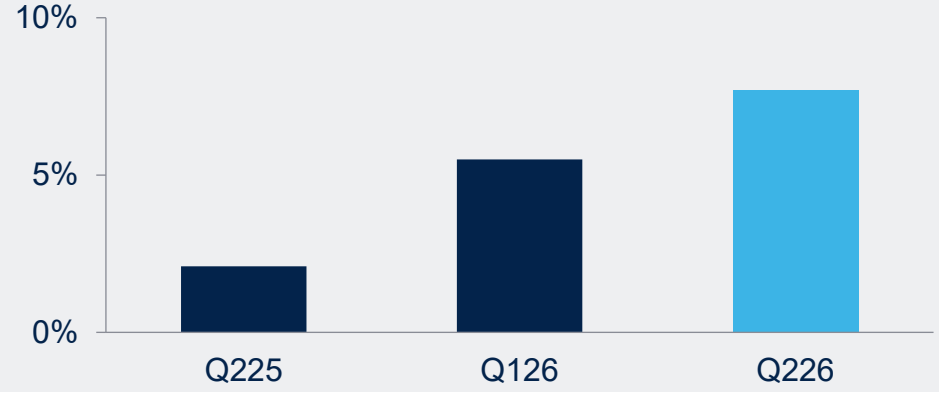


Q2 2026 Financial highlights

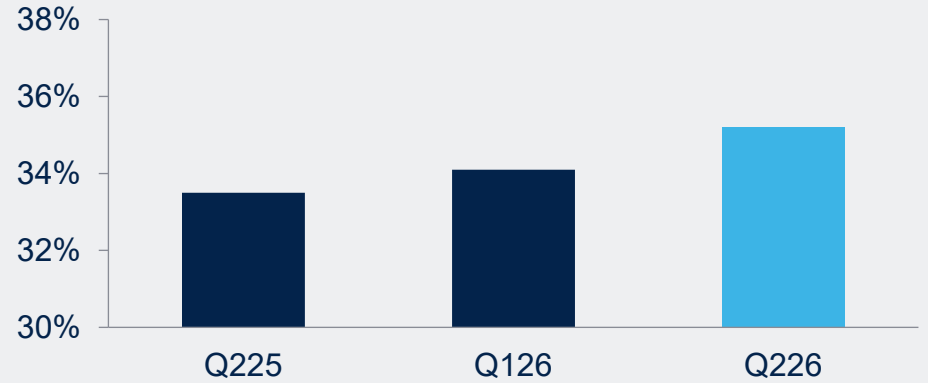
Revenues = $3.49B



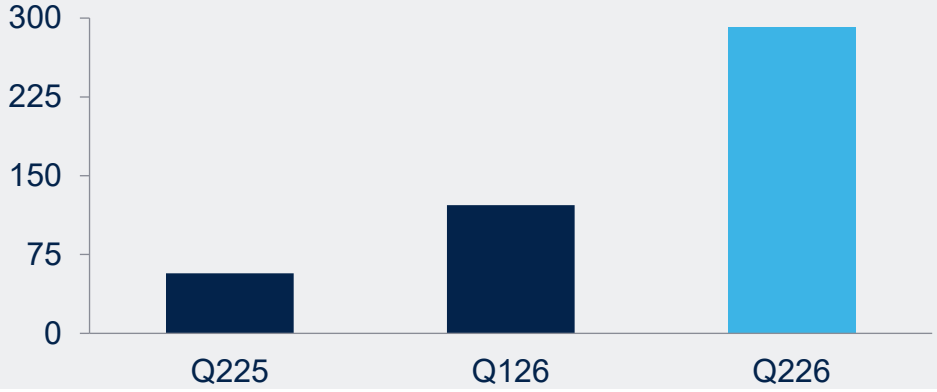
Non-U.S. GAAP Operating Margin* = 7.7%



Non-U.S. GAAP Gross Margin* = 35.2%



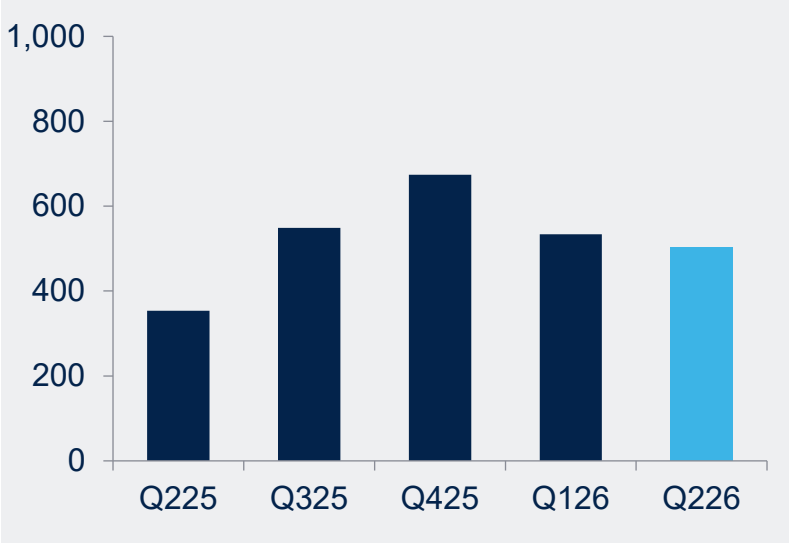
Non-U.S. GAAP Net Income* = $291M



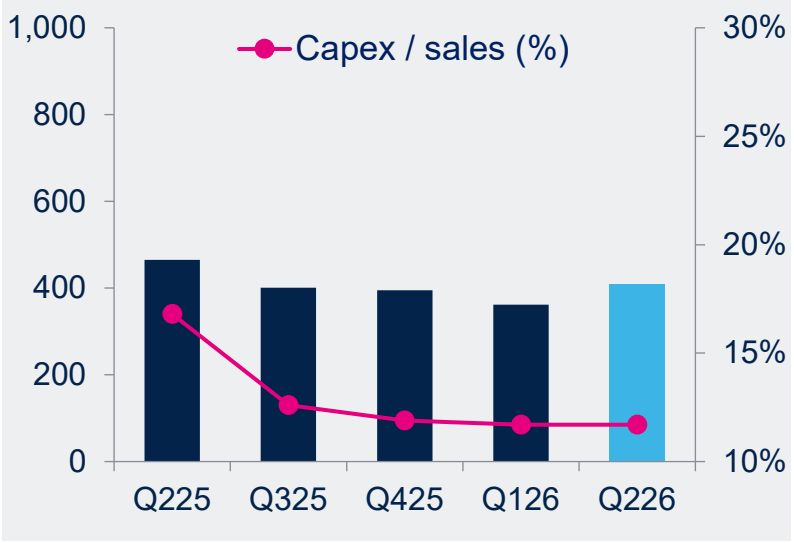
*__Non-U.S. GAAP measure__. See Appendix for additional information explaining why the Company believes these measures are important.

Q2 2026 Financial flexibility

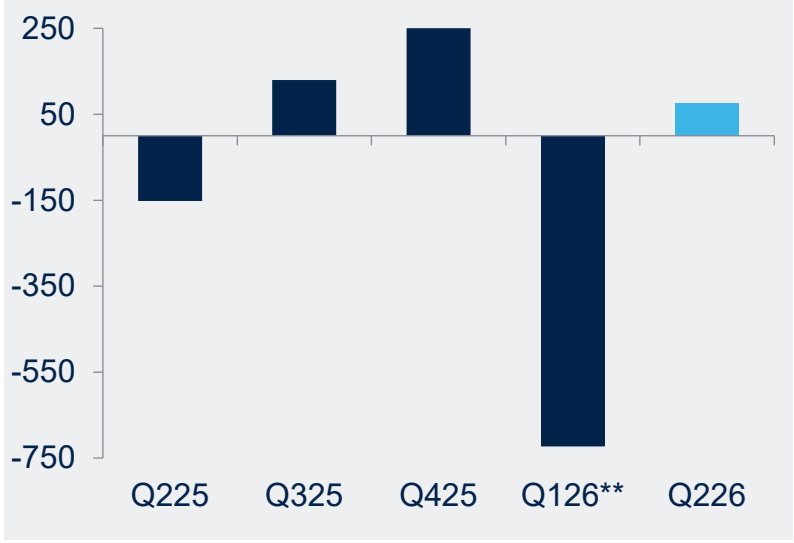
Net Cash From Operating Activities = $502M



Net Capex* = $409M



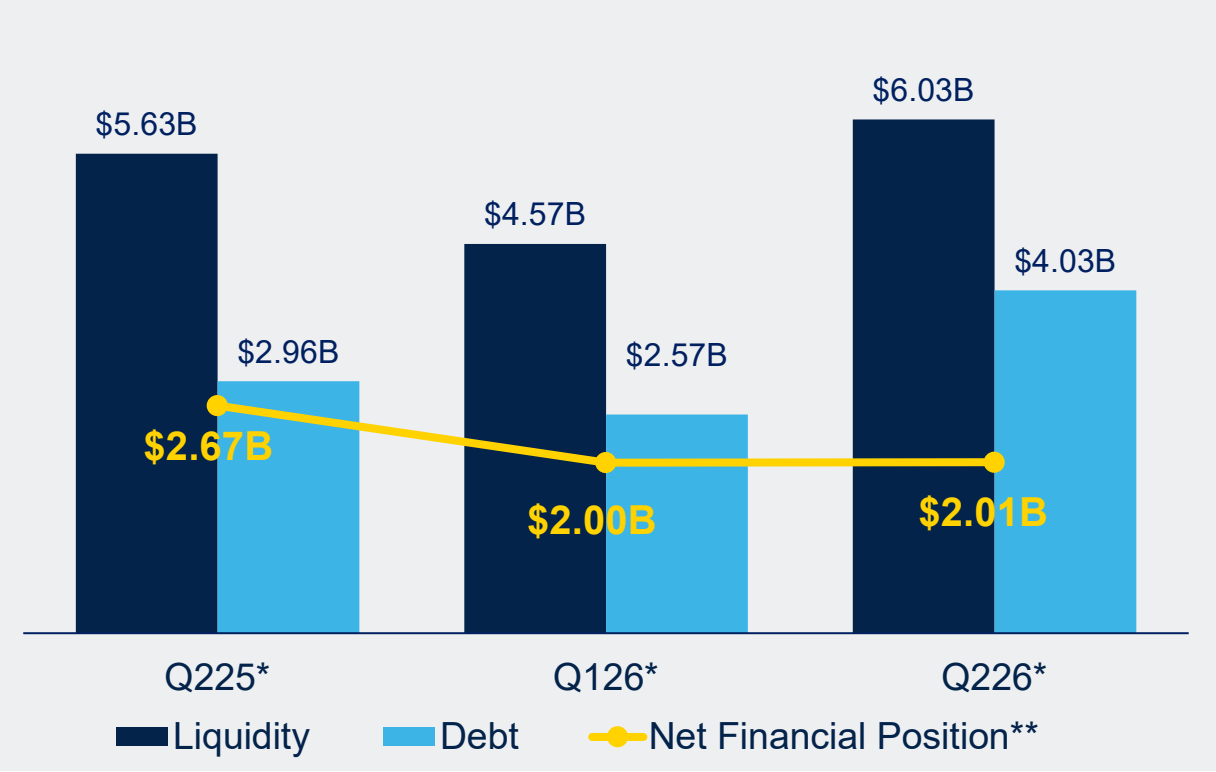
Free Cash Flow* = $75M



Cash dividends paid to stockholders totaled $75M in Q226.

*__Non-U.S. GAAP measure__. See Appendix for additional information explaining why the Company believes these measures are important.
** Q126 Free cash flow includes $895 million cash-out related to the acquisition of NXP MEMS sensor business.

Solid capital structure



ST is in a very solid position from a capital, liquidity and balance sheet perspective.

ST credit rating is currently BBB+ with Negative Outlook from S&P and Baa1 with Stable Outlook from Moody's.

*__Adjusted net financial position__, taking into consideration the effect on total liquidity of advances from capital grants for which capital expenditures have not been incurred yet, stood at $2.31B as of June 28, 2025, $1.69B as of March 28, 2026, and $1.70B as of June 27, 2026.
**__Non-U.S. GAAP measure__. See Appendix for additional information explaining why the Company believes these measures are important.

Q3 2026 Outlook

Net Revenues

Q326 outlook, at the mid-point, is for net revenues of **$3.70B**, increasing Y/Y by 16.2% and Q/Q by 6.2%, plus or minus 350 bps.

Gross Margin

Gross margin is expected to be **about 37.0%**, +/- 200 bps.

The third quarter will close on September 26, 2026.

This outlook is based on an assumed effective currency exchange rate of approximately $1.14 = €1.00 for Q326 and includes the impact of existing hedging contracts.

This business outlook does not include any impact for potential further changes to global trade tariffs compared to current situation.

Takeaways

In Q2 we saw demand further accelerating, strong bookings in all end-markets and improved visibility.

Q3 revenues expected to continue to grow Q/Q and Y/Y; and gross margin to continue to improve. Personal Electronics seasonality this year is different vs previous years. Revenue growth for Personal Electronics expected to be below normal seasonality in Q3, moderating ST's sequential growth in Q3.

In Q4 we anticipate revenue growth acceleration, mainly driven by AI datacenters and LEO satellite communication. Q4 revenues expected above $4B, representing a Q/Q improvement better than normal seasonality, translating into a H2/H1 growth above our normal 15% seasonality.

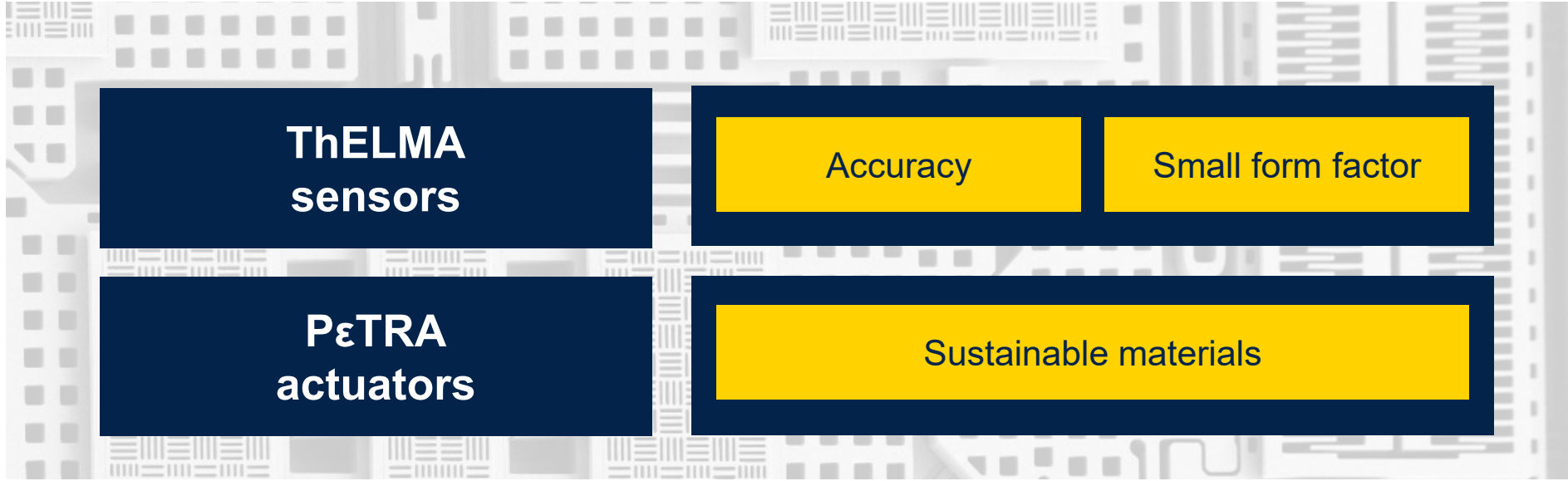
ST's growth drivers remain solid. We continue to see strong demand in AI datacenters and now expect revenues above $1B in 2026 and, assuming the current dynamic continues and with the current engagements we have, well above $2B in 2027.

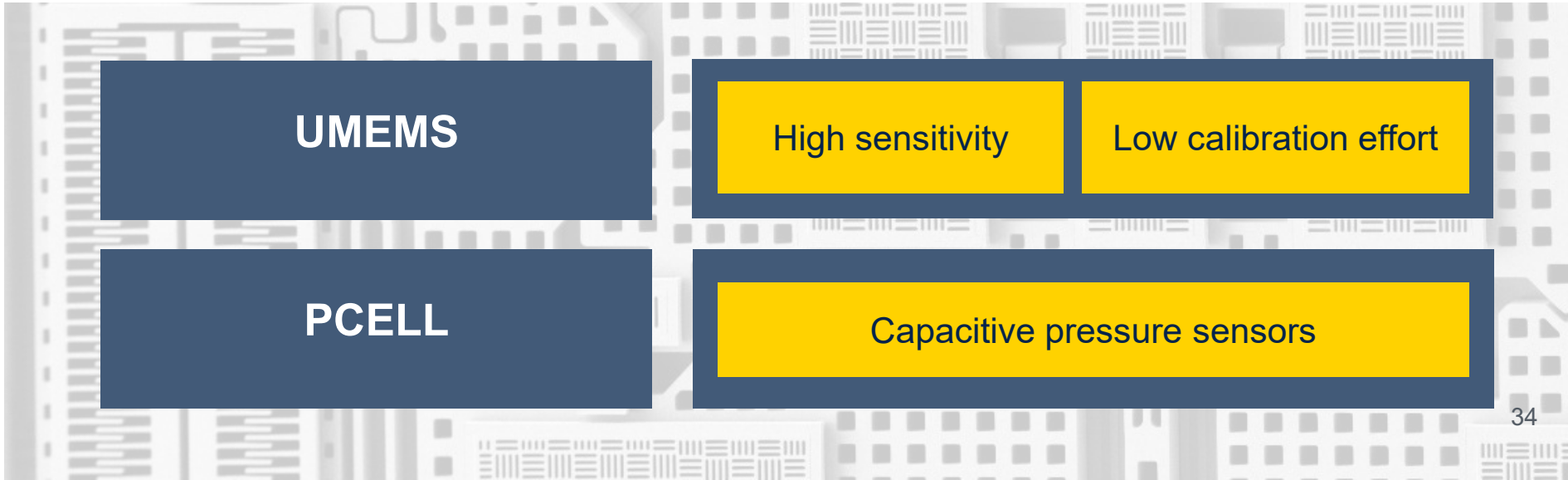
Recent transaction in MEMS
A highly complementary acquisition



MEMS technology portfolio further strengthened with the acquired business

Acquired Business





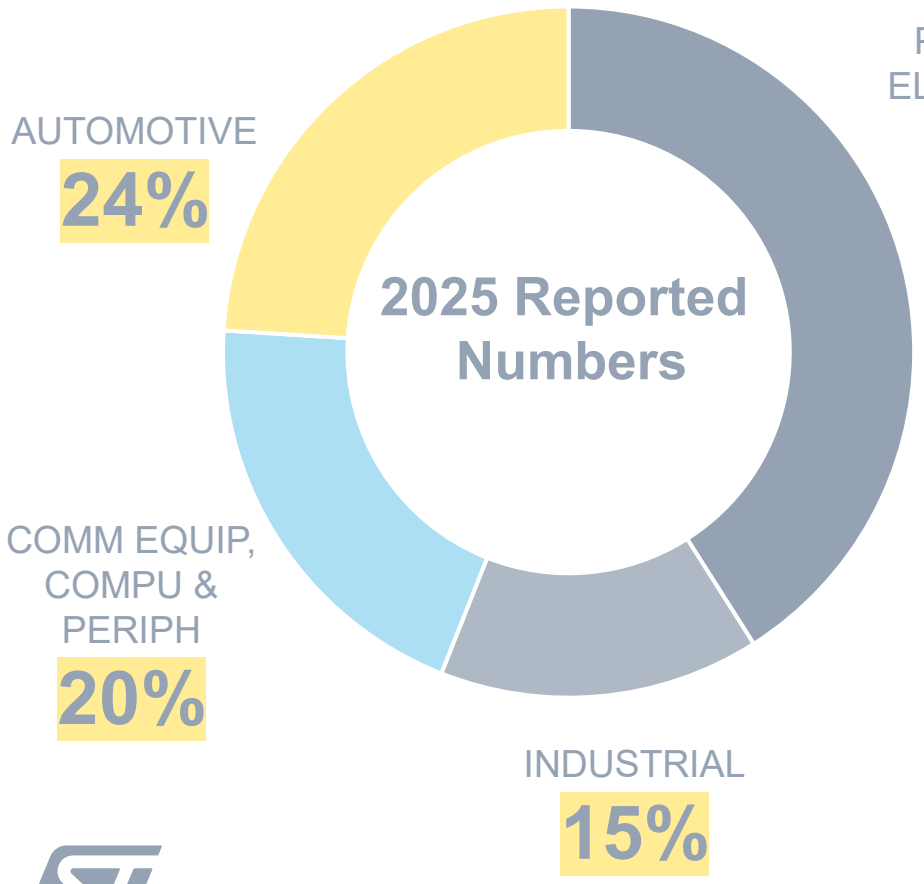
Complementary MEMS product portfolio …

		Acquired Business
#1 in MEMS sensors for Android	Personal electronics	-
#1 in MEMS for automotive navigation	Automotive	#1 accelerometer for safety In top 5 for pressure sensor
Applications specific solutions	Industrial	Solution for medical industrial
#1 in MEMS actuators printheads #1 in inertial MEMS sensors for laptop	Computer & Peripherals	-

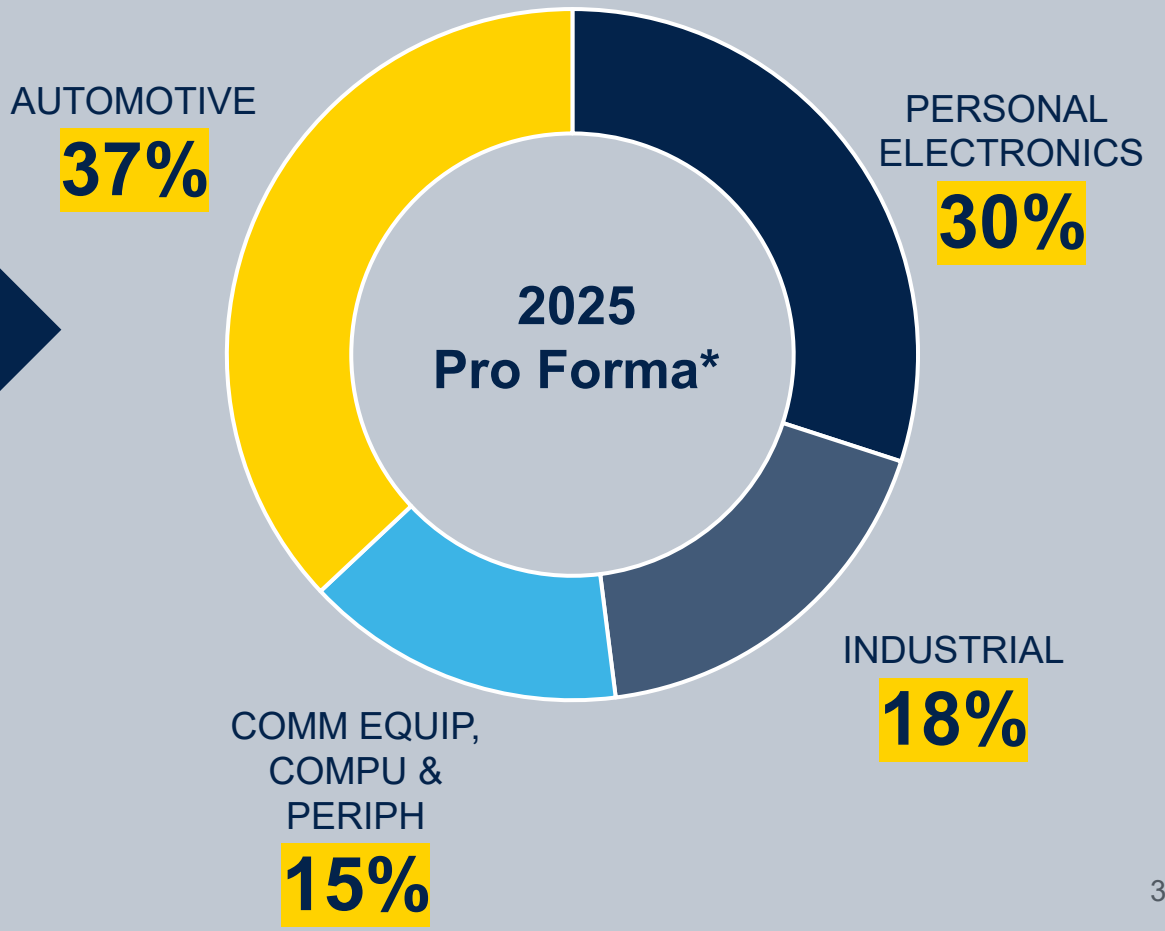
Source: Omdia, 2025 MEMS Consumer competitive landscape, ST

… rebalancing MEMS end-market exposure

Breakdown of MEMS revenues by end market

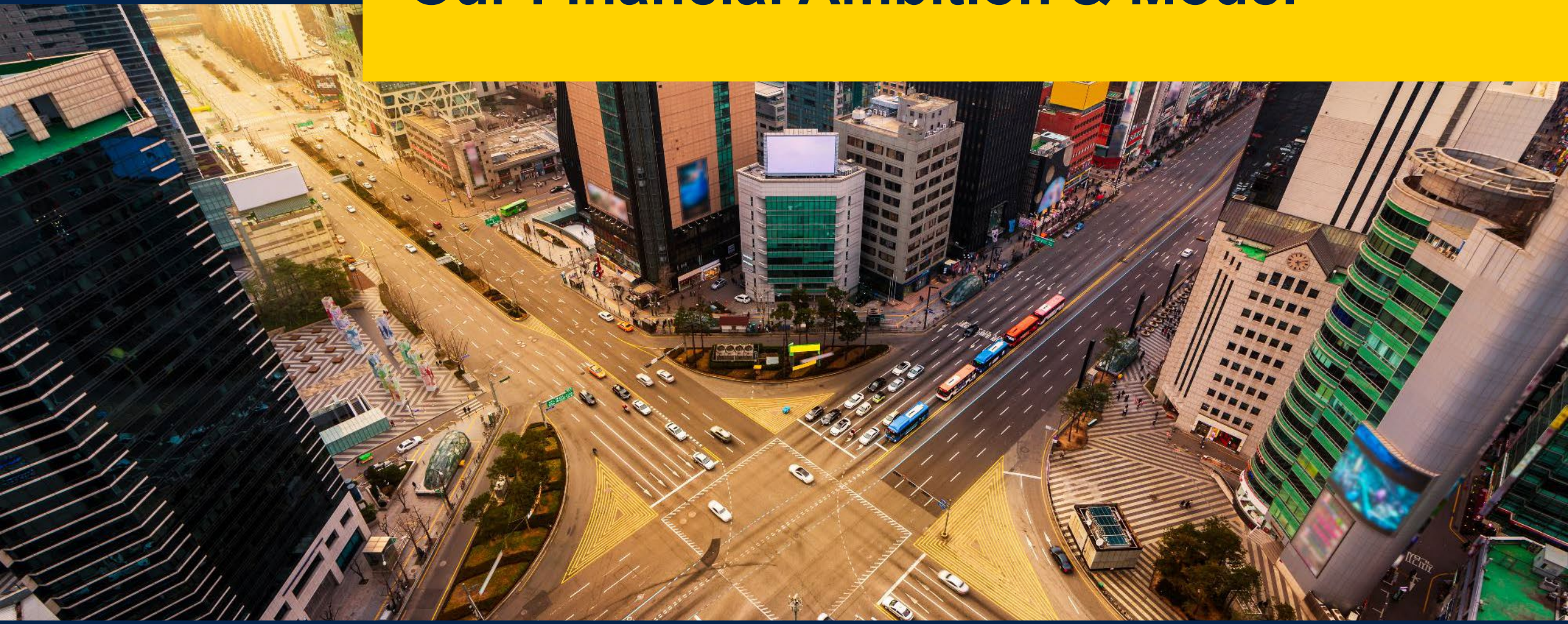






* Including acquisition of NXP MEMS Sensor business

Our Financial Ambition & Model



Summary

$20B+ Ambition and attendant financial model is still valid but postponed

Intermediate model with revenues expected at ~$18B in 2027 / 2028
ST has the right innovation capabilities, product portfolio, & end-market exposure to achieve this target

Gross Margin expected in a 44-46% range in 2027 / 2028
Supported by reshaping and improved efficiency of manufacturing footprint and to reach ~50% by 2030

Operating margin* expected in the 22-24% range in 2027 / 2028
Supported by resizing of our global cost base and to reach >30% by 2030

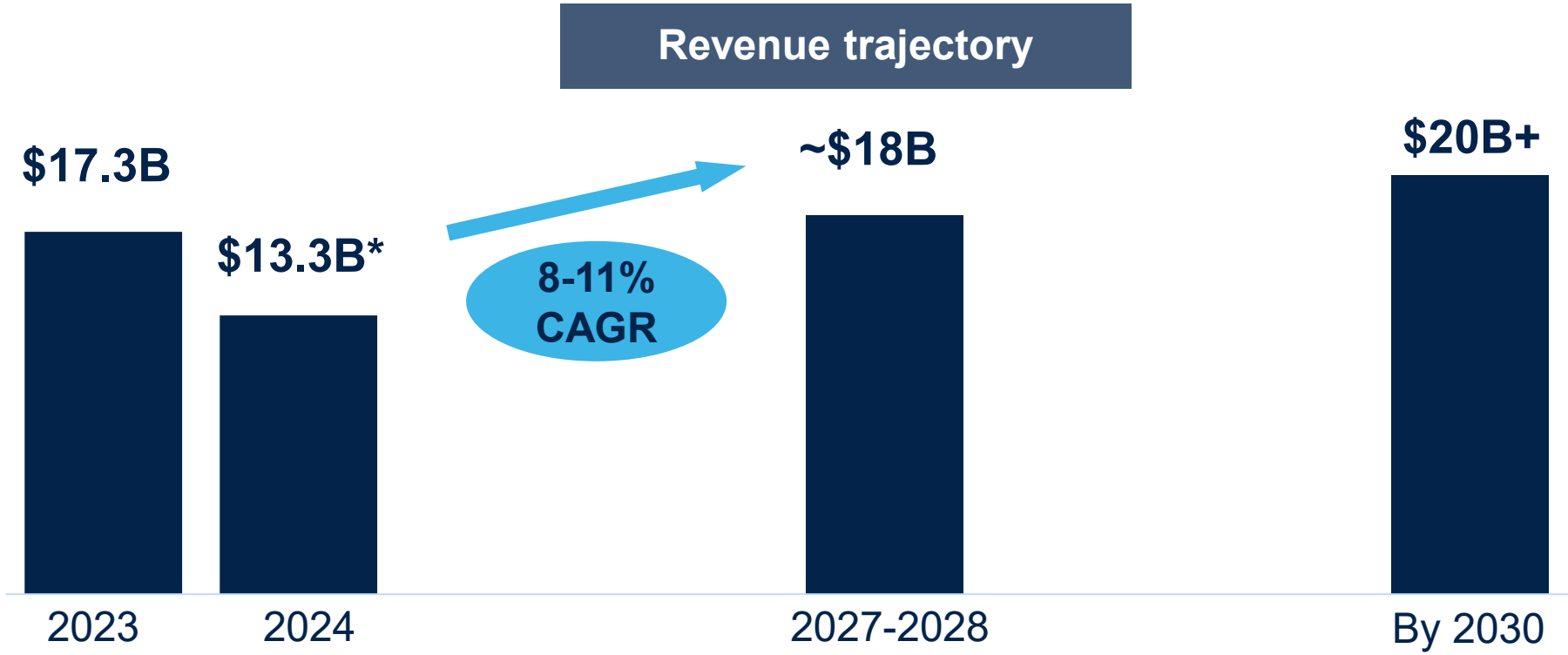
Improving FCF** to revenues ratio supported by increased profitability and lower capital intensity reaching 20%* of the revenues in 2027 / 2028 and >25% by 2030

* Excluding one-offs

Non-U.S. GAAP measure. See Appendix for additional information explaining why the Company believes these measures are important.

Source: STMicroelectronics Capital Markets Day 2024

The $20B+ ambition is postponed but still intact
A new intermediate point in FY 2027/2028 is set



Considering a changing market and competitive environment, we set a new intermediate Financial Model on the path towards the $20B+ ambition by 2030

Source: STMicroelectronics Capital Markets Day 2024

Introducing a new intermediate financial model towards the $20B+ financial ambition

	Key financials	
	Intermediate model (2027/28)	**$20B+ ambition (by 2030)**
Revenue	**~$18B**	**$20B+**
Gross Margin	**~44-46%**	**~50%**
Operating Margin	**~22-24%***	**>30%**
Free Cash Flow Margin**	**~20%***	**>25%**

Financials assume a currency exchange rate of approximately $1.09 = €1.00. See appendix for FX sensitivity

* Excluding one-offs

****Non-U.S. GAAP measure**. See Appendix for additional information explaining why the Company believes these measures are important.

See Forward Looking Information for full disclosure. Such information is subject to various risks and uncertainties, which may cause actual results and performance of our business to differ materially and adversely from the Forward Looking Information.

Source: STMicroelectronics Capital Markets Day 2024

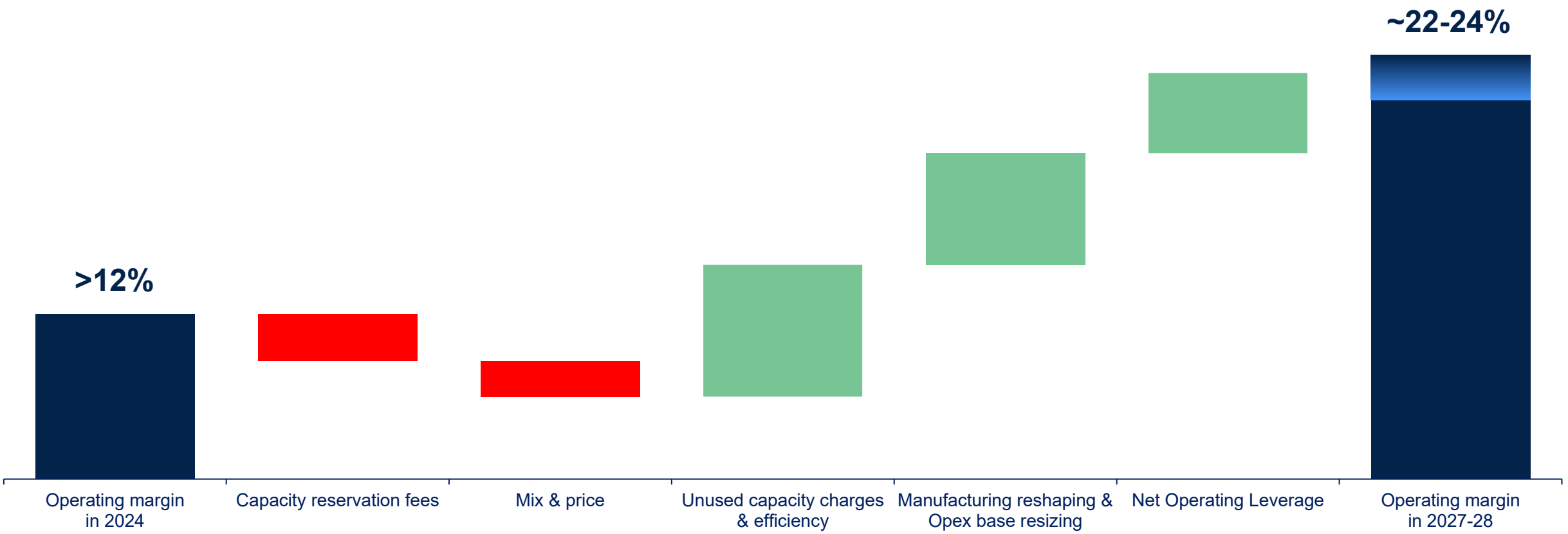
Strengthening revenue growth capability and improving operating efficiency

Implementing new organization	Delivering **enhanced product development innovation and efficiency**, time-to-market as well as **customer focus** by end market.
Reshaping of manufacturing footprint	Improve **productivity / efficiency** of our fabs
Resizing of global expense base	Generate structural **cost savings**

ST is adapting to a lower-than-expected revenue base by managing what is under our control

Source: STMicroelectronics Capital Markets Day 2024

Key drivers of operating margin improvement



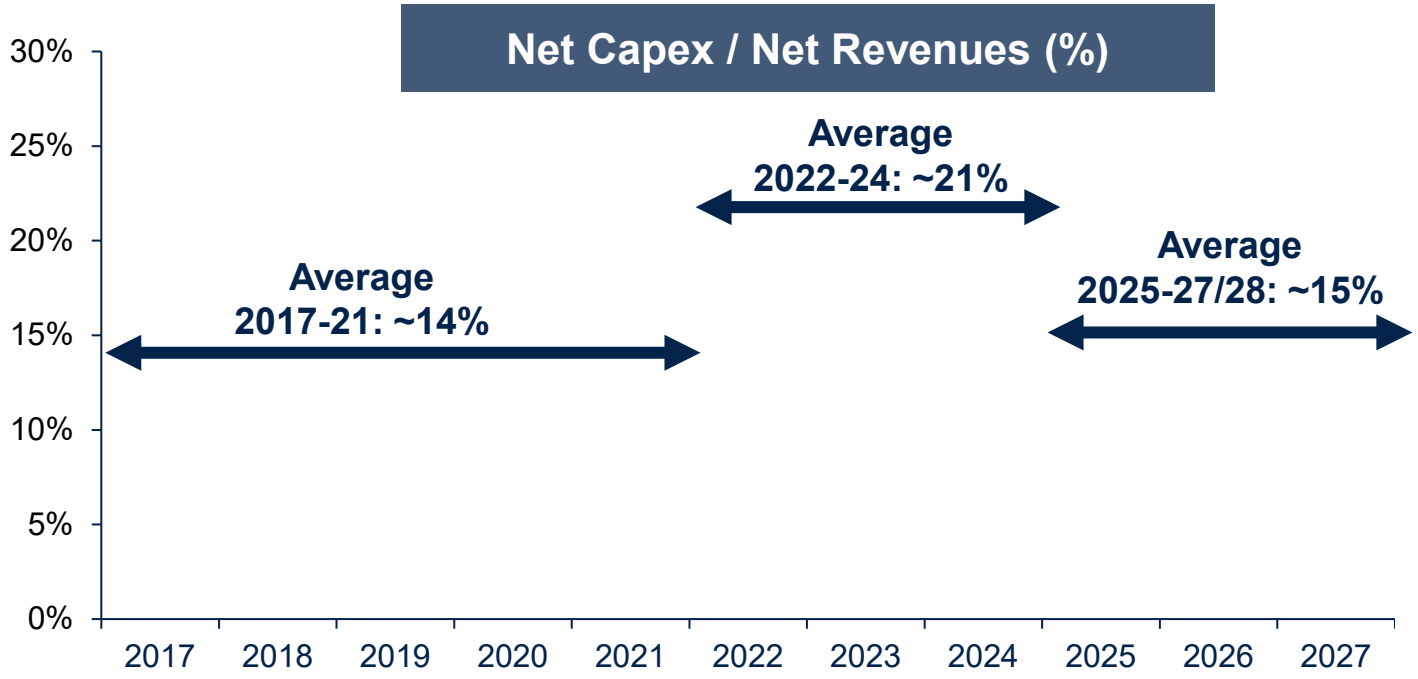
Unused capacity charges & efficiency, cost base resizing and operating leverage are the key drivers of operating margin improvement

See Forward Looking Information for full disclosure. Such information is subject to various risks and uncertainties, which may cause actual results and performance of our business to differ materially and adversely from the Forward Looking Information.

Source: STMicroelectronics Capital Markets Day 2024

Capital intensity is expected to decrease

We are in a position to leverage the significant investments in the infrastructure done in the last few years



Main investments 2024-27

Capacity & mix Changes
- Agrate and Crolles 300mm
- Assembly & Testing

SiC
- Catania fully integrated 200 mm facility
- JV with Sanan (200 mm)

Maintenance, efficiency improvement, R&D, CO_2 neutrality program & others

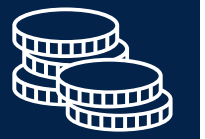
Improving FCF* to revenues ratio reaching 20% of revenues by 2027/2028

* Excluding one-offs

See Forward Looking Information for full disclosure. Such information is subject to various risks and uncertainties, which may cause actual results and performance of our business to differ materially and adversely from the Forward Looking Information.

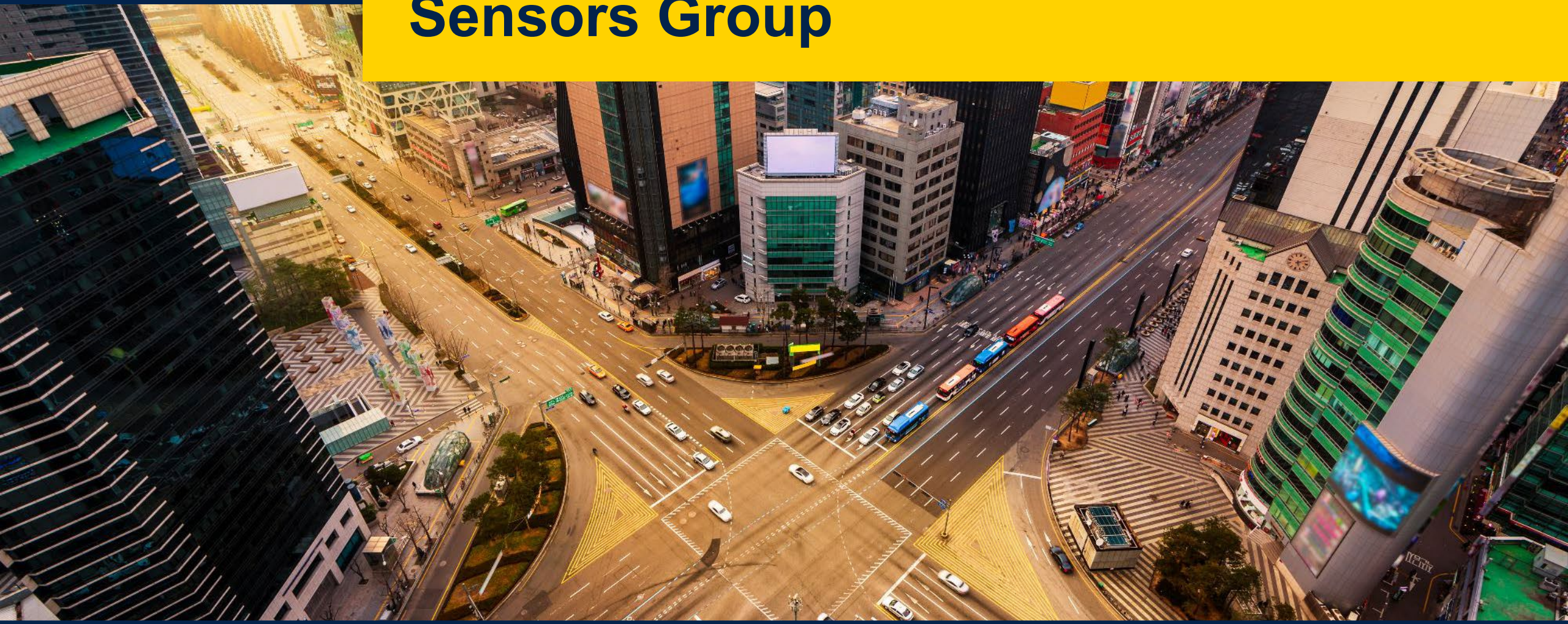
Source: STMicroelectronics Capital Markets Day 2024

Investment & capital allocation

Commitment to innovation and growth 	Market-driven R&D based on leading-edge products and technologies Accelerate R&D investment on critical success areas: wide bandgap materials, Edge AI, Silicon Photonics, Cloud-Connected Autonomous Things…
Organic growth 	Commitment to organic and self-financed growth complemented by strategic partnerships with Foundry and OSAT Accelerated transition towards 300 mm Silicon and 200 mm SiC
Strategic M&A 	Fast bolt-on specialized acquisitions to boost innovation, reinforce our IP and product portfolio
Balance Sheet 	Maintain solid capital structure and financial flflexibility Investment-grade credit ratings
Shareholder returns 	Return value to shareholders improving Company fundamental value Dividend policy consistent with our planned increased cash generation

Source: STMicroelectronics Capital Markets Day 2024

Analog, Power & Discrete, MEMS and Sensors Group



APMS product portfolio

Power

Power transistors



- Silicon MOSFETs
- IGBTs
- SiC MOSFETs
- GaN FETs
- Intelligent Power Modules
- Power Modules

Discrete & filter



- Thyristor & Triac
- Ultrafast & SiC Diodes
- Power Schottky
- Protection & ASIPs
- RF Integrated Passive Devices & Filters

Analog

Application specific



- Automotive: Battery Management, Traction, Braking, Airbag, Door Zone, Engine, PMIC
- Industrial: Motion control, Galvanic Isolated, Digital power, Smart Power GaN, PMIC, Medical ICs
- Storage & Server: PMIC, PreAmps
- Personal device: wireless charging, touch controller, display PMIC

General purpose



- AC-DC, DC-DC
- MOSFET, IGBT, SiC, GaN Gate Drivers
- Intelligent Power Switches, High- & Low-side drivers, LED drivers,
- Op Amps, Vref, Vreg, LDOs eFuses, current sensing,
- Real Time Clocks and Timers, Supervision, Control ICs

Sensors

MEMS



- Smart sensors
- Biosensors
- 6-axis Inertial measurement unit
- Accelerometer & gyroscopes
- Vibrometers, Inclinometers
- Barometers, pressure,
- Temperature, electrostatic
- Magnetometers

Imaging



- CMOS image sensors
- 3D Camera
- ToF sensors
- Ambient light sensors
- Proximity sensors
- Micro-optics
- Custom optical solutions

Source: STMicroelectronics Capital Markets Day 2024

APMS product strategy

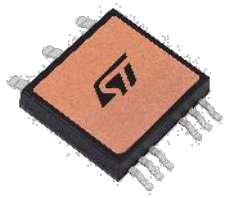
Broad product portfolio

15,000+ products

Power
Power transistors
Discrete & filters

Analog
Application specific
General purpose

Sensors
MEMS sensors & actuators
Optical sensing solutions









Focused market approach

$100B+ SAM

100,000+ Customers

Strategic **focus on industrial & automotive** end markets

Address specific high-volume opportunities in **personal electronics**

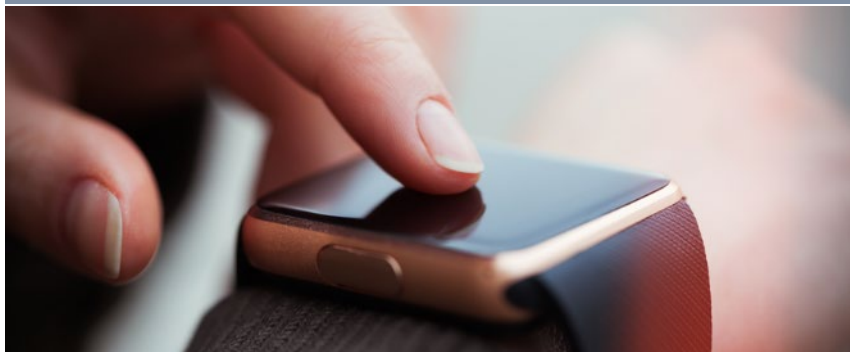
Selective approach in **communications equipment and computers & peripherals** focusing on advanced power management

OEMs and distribution

Leveraging our proprietary technologies and integrated device manufacturer model

Source: STMicroelectronics Capital Markets Day 2024

APMS growth stems from key trends

Smart Mobility	Power & Energy	Intelligent Things
		
Safer Greener More connected	Greener generation Smarter transmission Efficient utilization	Intelligent Sustainable Transformative

Smart mobility trends driving car architecture and technology evolution

Safer	More connected	Greener
Enhanced safety features Advanced driver assistance systems Self-driving vehicles	Connected vehicles Digital experience Post-purchase Services	Electric vehicles Stricter emissions standards Alternative fuels

Extended features Improved safety More electronics	Digitalization	Electrification
Smart lighting	SW-defined vehicles Domain / Zonal architecture	Full electric
Braking systems	ADAS / Autonomous vehicles	Mild Hybrid EV 48V

Proliferation of sensors

In-car networking evolution

Security

Source: STMicroelectronics Capital Markets Day 2024

SiC market dynamics and strategic focus

Recent trends

Global **EV growth pace** and shift of focus to **hybrid models**

Evolving **customer landscape** in the automotive market

Slower than expected **industrial recovery**

Strong growth of **AI server market**

Increasingly **competitive market**

Strategy & Ambition

Back to 2024 revenues in 2027

Strong long-term growth of the SiC market

~30% long-term market share **ambition**

ST's **manufacturing strategy**

- Full vertical integration – from powder to modules
- SiC Campus Catania facility
- 200 mm wafer transition
- Joint-Venture with Sanan for front-end and assembly & test at ST Shenzhen for China

Growth and diversification of customer base including industrial applications & AI servers

Continuous **technology innovation**

Winning in smart mobility

Large and growing opportunity thanks to transformation of industry
Targeting to grow 2x the market

Strong customer base

Over 30 years of automotive experience

Strong relationships with key automotive car makers and tier1's across regions

Innovating with market shapers



Key technologies

SiC discretes and module

Vertical Integrated Power

BCD for automotive

MEMS & optical sensing

Application knowhow

Shift from customer-driven product to application driven products

Leverage broad and deep knowledge of automotive systems to develop solutions optimized for targeted subsystems

Localized technical support

Manufacturing capacity & resilience

Vertically integrated SiC manufacturing

In-house front-end and back-end technology & owned capacity

China-for-China end-to-end strategy

Products

Application-specific and general-purpose analog and power product roadmaps fitting diverse E/E car architectures

Anticipating further car architecture evolution

Sensors enabling a broad range of applications

Source: STMicroelectronics Capital Markets Day 2024

Power & energy trends



Greener generation

Rising demand

Renewable sources

Reducing emissions



Smarter transmission

Smart grid technologies

Smart buildings and IoT

Charging infrastructure



Efficient utilization

More power-hungry factories, servers..

Better use of every watt

Efficient energy conversion

Source: STMicroelectronics Capital Markets Day 2024

Power: challenges and architecture (r)evolution

Today – 2025 / 2026

Power: **130 kW – 288 kW**



HV Grid

Low Frequency Transformer

400V AC

server

PSU (AC/DC)

54V

DC/DC

12V

Multiphase
Voltage regulator

GPU

Challenges

Growing xPU compute

Size/Space

Conversion Efficiencies/Losses Thermal management

Evolution – 2027 and beyond

Power: **500 kW – 1 MW+**

HV Grid

SST* : High Frequency Transformer + AC/DC

Solid State Circuit Breaker

800V DC

server

DC/DC isolated

54V / 12V / 6V

DC/DC

12V / 6V / 3.3V / 1.7V

Multiphase
Voltage Regulator

GPU



Unlocking 1MW+ rack density through power technologies: Wide bandgap, galvanic isolation and smart power

SST: Solid State Transformer

ST offering from grid to core power delivery

800V AC-DC

PSU for power shelf applications



High-efficiency and density AC to DC conversion

- Based on SiC/GaN for optimized efficiency and power density
- 8.5-12 kW and beyond capability supporting power shelf configuration
- Low profile solution enabling better cooling

800V to 54V

12 kW High density converter



High-efficiency and density 800V DC to DC

- Compact, high-power density
- GaN MOSFETs enable 1 MHz frequency operation minimizing size of magnetic
- Wide range & high output voltage

54V to 12V

2 kW GaN-based “HV Buck”

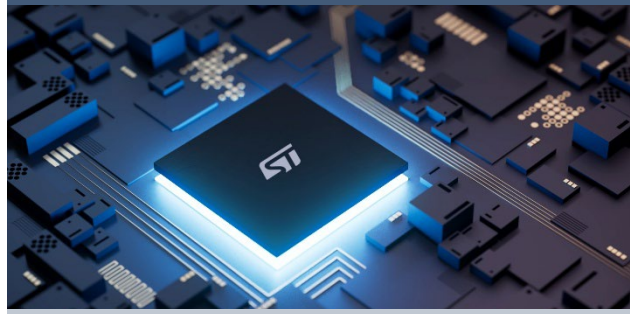


High-efficiency and density intermediate bus converter

- Higher power density achieved using GaN devices
- Wide input (36-60V) and regulated 12V output

12V to 0.8V

Digital multiphase controller and SPS



STVCOT control loop with SPS

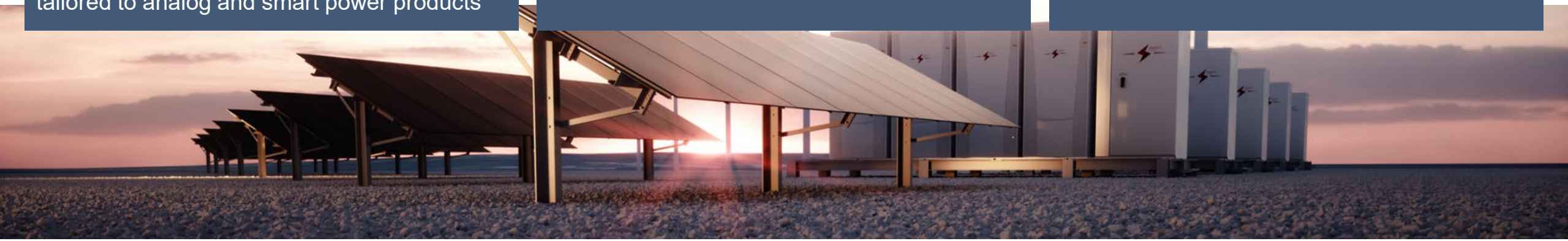
- Total solution for 12V to xPU core efficient power delivery
- Supporting up to 32 phase VR configuration for high-power xPU
- Compliant with Intel, AMD, and Arm®-based CPU

ST covers the complete datacenter power chain, combining SiC, GaN, low-voltage devices, systems in a fully integrated solution

Winning in power & energy

Growing and fragmented market
Target low teens growth in line with the market

Strong technology roadmaps	Wide portfolio	Go-to-Market strategy
Wide power process technology from low to high power, from silicon to wide bandgap	15,000 products to support growing applications	Addressing both OEMs and distribution
Power package portfolio supporting SiC and GaN roadmaps	Covering full product span: sensing, controller, driver, power stage	Leveraging large portfolio to deliver solutions
Broad front and back-end technology portfolio tailored to analog and smart power products	Large set of IP to further enlarge portfolio	System and application knowhow
		Localized skilled technical support in all regions



Source: STMicroelectronics Capital Markets Day 2024

Sensors at the intersection of structural growth trends across multiple end-markets



Our ambition in sensors: Outgrowing the markets we serve



Aim to grow our sensors* revenues at a **mid-teens CAGR** between 2025 and 2028**, with further opportunities to grow beyond this time horizon

* MEMS + Imaging
** from a base of $2.2B in 2025

Winning in intelligent sensing

Intelligent sensing is essential for AI….
… and AI will drive future sensor growth with intelligence at the edge

Strong technology & products roadmaps

- #1 European IDM for optical sensing technology
- MEMS & Imaging dedicated technology platforms & teams
- Sensor product roadmaps leveraging ST CMOS technology

Partner with market shapers

- Intimacy with key players, engaged key customer programs
- Standard & custom solutions tailored for specific applications
- Deep engineering expertise



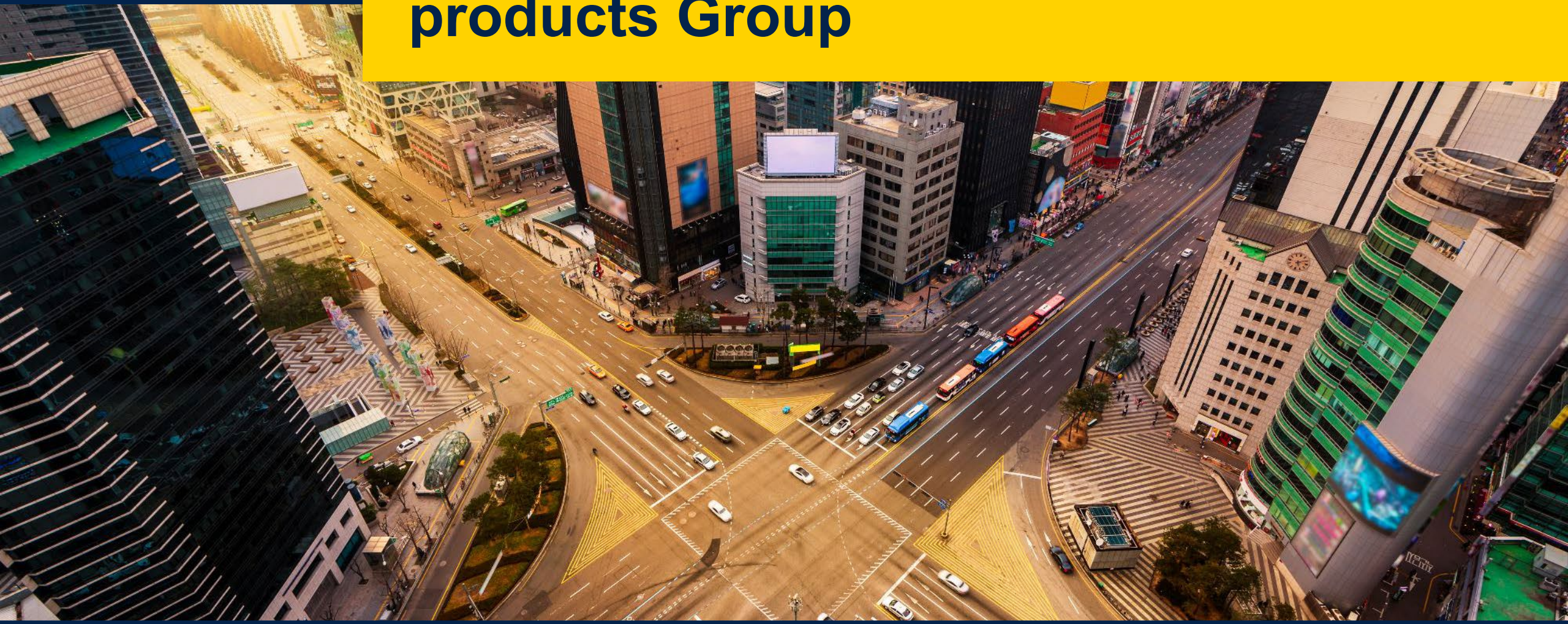
In-house manufacturing capacity

- Proprietary front-end & back-end technology
- Proven & scalable EU based front-end capacity
- 300 mm fabs
- Able to ramp in line with customer expectations

Differentiated products

- Broadest industry sensor provider
- Large set of reusable analog & sensing IP
- Embedded processing & edge AI tools and ecosystem
- Enabling multiple innovative applications

Microcontrollers, Digital ICs and RF products Group



MDRF Product Group focus and ambition



Continuously focus our R&D on markets where we are or we can become #1 or #2, accretive to ST GM and OM margin targets and leveraging our IDM model

Leverage ST differentiated technology and manufacturing platform to:

1. Grow our GP MCU 1.5x faster than the market over 2017-2027
2. Build a leading position in automotive MCU
3. Sustain our secure MCU position

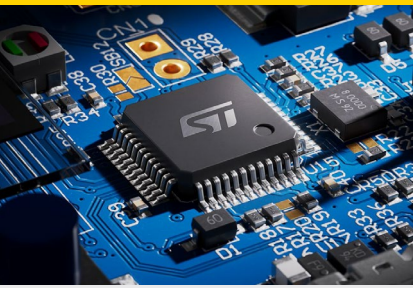
Stay #1 and continue to expand our presence in the fast-growing LEO market

Become #1 in AI cloud interconnect market through hyperscaler collaborations

MDRF product portfolio

Embedded processing (Microcontrollers reporting segment)

General-purpose MCU & MPUs



STM32 32-bit general-purpose MCUs and 32/64-bit MPUs

Arm® Cortex® cores

High performance, mainstream, ultralow power MCU offer
Graphics & AI accelerators

Wireless MCUs (BLE, WIFI)

Extensive ecosystem with edge AI

Automotive MCUs & Custom processing



Scalable single- and multicore MCU solutions,

Targeting cost-sensitive to highly advanced applications &

Supporting next-generation SDV architectures and X-in-1 approach.

Comprehensive SW development ecosystem

ADAS image signal processors

Secure solutions



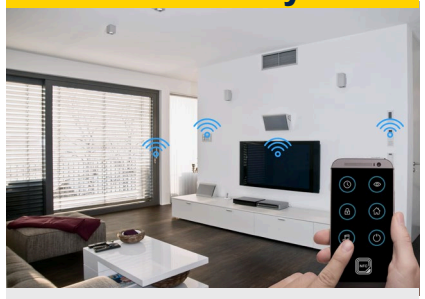
Mobile consumer transactions.

Authentication and brand protection.

Payment systems solutions.

Connected security for automotive.

NFC & Memory



NFC / RFID Tags

Dynamic NFC tags

NFC / RFID Readers

High-performance & high-endurance EEPROMs

RF & Optical Communications

RF



Developing solutions based on proprietary FD-SOI & BiCMOS technologies for

Satellite communication

Satellite radio

Positioning

Automotive Radar and UWB

Connectivity modules

Audio amplifiers

Optical Communications



ASICs for data center optical networking

Advanced Silicon Photonics and BiCMOS technologies to enable the next generation of cloud interconnect

Dedicated optical transceiver solutions

The trends we intend to benefit from

AI at the (tiny) edge



Enables more energy-efficient & smarter decision making

Reduces decision latency & data transferred to the cloud

Enhances privacy and security

Electrified & software defined vehicles



Are flexible & upgradable: with over-the-air updates & modular improvements

Provide enhanced safety & security: Predictive maintenance & adv. security.

Have innovative features: autonomous driving & personalized experiences.

LEO satellite constellations



Connect the unconnected:

- **Ensure** global coverage
- **Provide** high-speed internet to remote and underserved areas worldwide

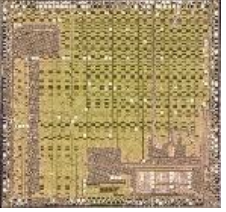
Cloud optical interconnect



Cloud requires increasingly higher comm. bandwidth w/i and between AI data centers (DC)

Cloud power consumption growth has to be mitigated

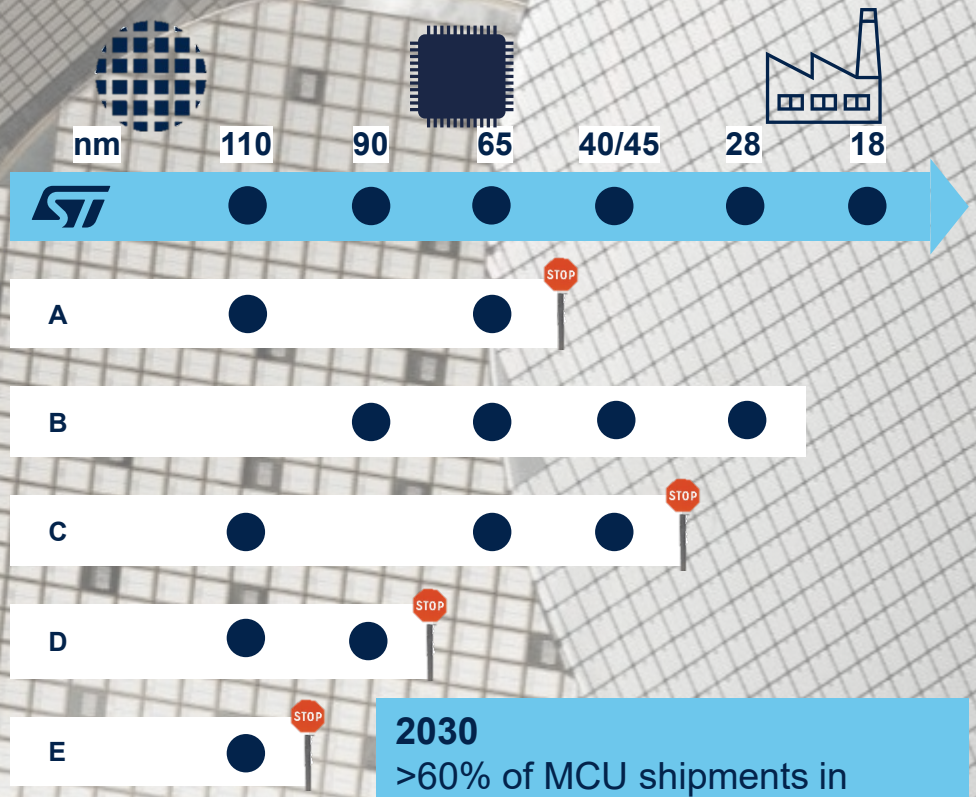
Silicon Photonics will become the technology linchpin of the AI cloud



What's unique about ST in microcontrollers

MCU key success factors	Why ST
Manufacturing capacity, and resilience	In-house silicon technology & capacity in Europe, External fab partners, China for China
eNVM technology	40 nm eNVM in production **28 / 18 nm ePCM** ramping
AI HW acceleration & SW stack	Most **comprehensive MCU HW and SW stack** in the industry
Developers' productivity →customer stickiness	Most advanced **MCU ecosystem** 1.6M unique developers
Security	State of the art IP (inc. PQC) for a scalable, future-proof and easy to use MCU security offering
System-level solutions	Wide ST product portfolio: MCU + sensing, analog, power, actuation, etc.

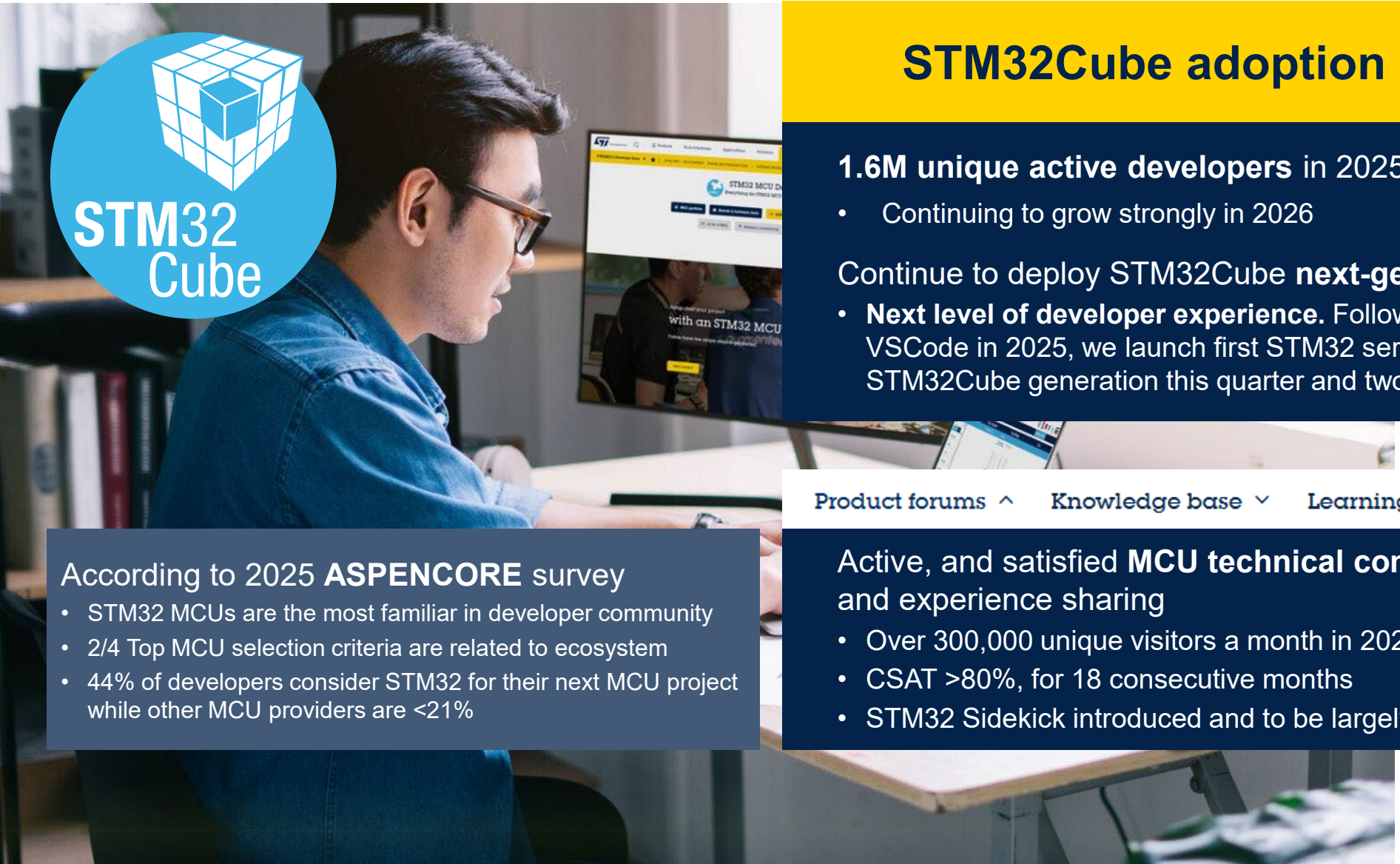
eNVM CMOS process in-house technology



2030
>60% of MCU shipments in technologies at 40 nm and below
Source: Yole Q3'24 and ST estimate

Source: STMicroelectronics Capital Markets Day 2024

A developer-first mindset with STM32Cube
The world largest MCU software ecosystem platform



STM32Cube adoption is accelerating

1.6M unique active developers in 2025 - **25%** YoY growth

- Continuing to grow strongly in 2026

Continue to deploy STM32Cube **next-generation platform in 2026**

- **Next level of developer experience.** Following the launch of STM32Cube for VSCode in 2025, we launch first STM32 series fully supported by evolved STM32Cube generation this quarter and two other series to follow in 2026

According to 2025 **ASPENCORE** survey

- STM32 MCUs are the most familiar in developer community
- 2/4 Top MCU selection criteria are related to ecosystem
- 44% of developers consider STM32 for their next MCU project while other MCU providers are <21%

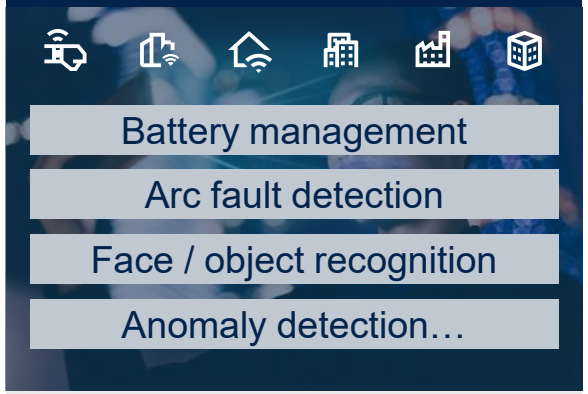
Product forums | Knowledge base | Learning | About | Developer news

Active, and satisfied **MCU technical community** for learning, support, and experience sharing

- Over 300,000 unique visitors a month in 2025
- CSAT >80%, for 18 consecutive months
- STM32 Sidekick introduced and to be largely deployed in 2026

Making AI @ the tiny edge… a reality

Increasing adoption of edge AI solutions



↗ 113% CAGR to 2030
for TinyML MCUs
(ABI Research)

More inference tasks will be handled **locally**, which will help **reduce the strain** on the global power grid

Significant growth in developer engagement



180K **Active projects on ST's AI tools over 12 months**
by end 2025

Partnering with AI industry **leaders**

NVIDIA
aws

A roadmap for the most challenging workloads



Neural-ART 1
→ up to **4.6 TOPS**
→ 1 to 5 TOPS/W

Neural-ART 2 (D-IMC)
→ **X 4 ***
→ 20 to 40 TOPS/W

Neural-ART 3 (Hybrid)
→ **X 10 ***
→ 50+ TOPS/W

All performances expressed in 8 bits
** Performance gain vs Neural-ART 1*

Introducing STM32N6 with Neural-ART 1



600x Performance gain vs best STM32H7

$100M One of the **fastest** products to reach **$100M** in STM32 history

STM32 China-for-China game plan
Growing local customers base 50% by 2030

Creating a differentiator that will help us gain market share with Chinese and global customers

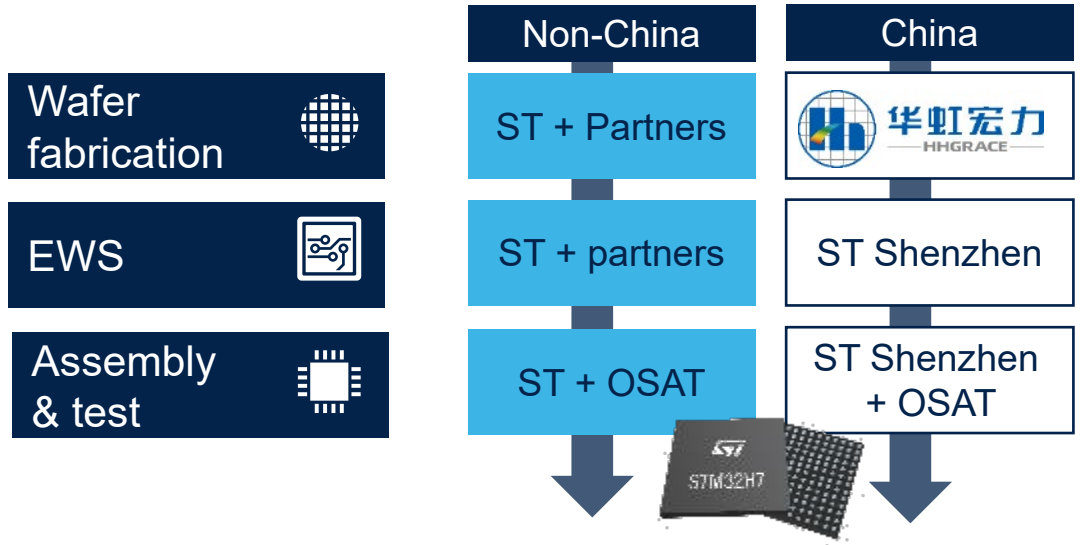
Support growing need of Chinese and global customers for a **fully localized supply chain**

Exact same eNVM 40 nm STM32 manufacturable in Europe or in China (same mask set!)

Objective to serve **majority of eNVM 40 nm STM32 China business from China** in medium term

First deliveries of fully made-in-China STM32 microcontrollers to China-based customers started

ST eNVM 40 nm dual-supply chain

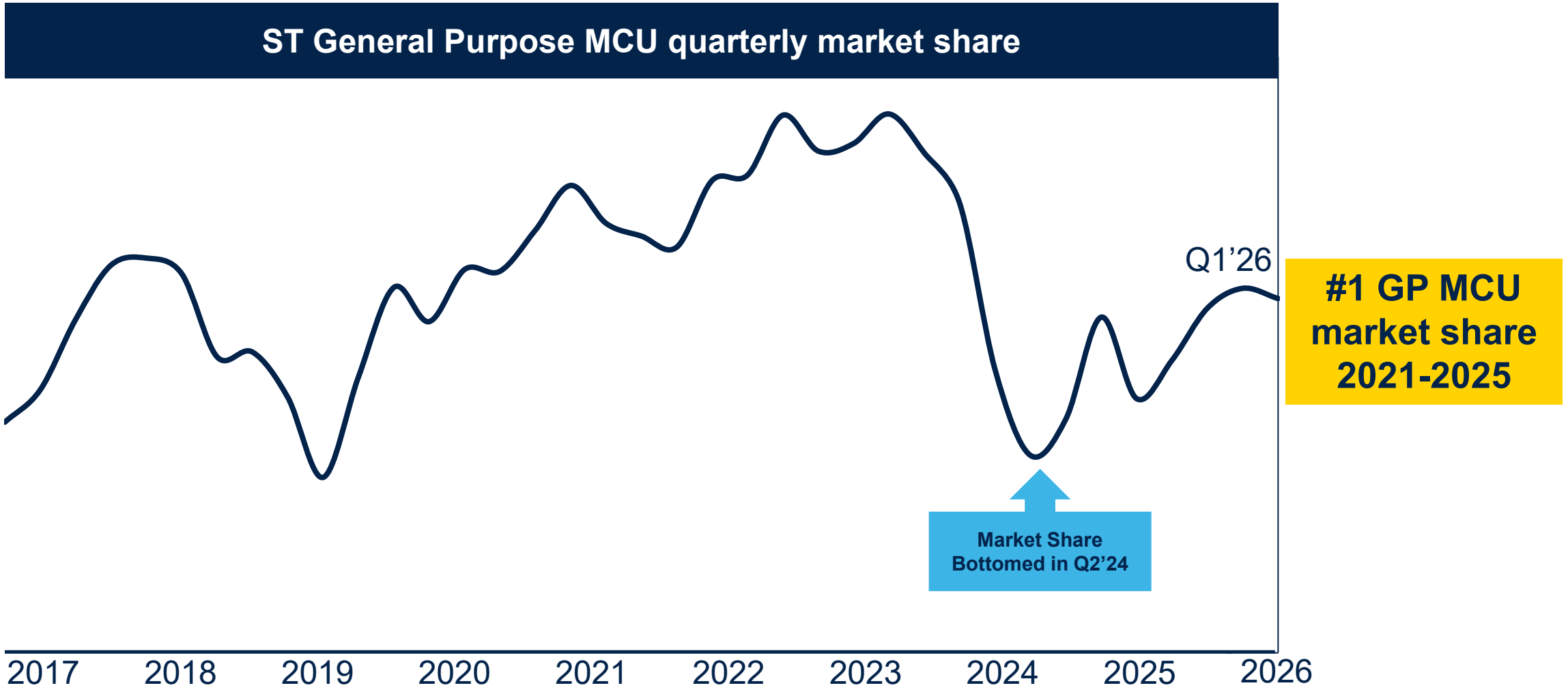


Examples of supporting Chinese and global customers

Danfoss, Elitech, 锦浪科技 GINLONG, GOODWE 固德威, Gospower, Growatt, HoT 和而泰, 欧陆通 HONOTO, Hisense Broadband 海信宽带多媒体, Husqvarna Group, 盈趣科技 Intretech, invt, jiaxipera 加西贝拉, 精创 股份 Since 1996, KCFA, Panasonic, RUKING 儒竞科技, Schneider Electric, SIEMENS

Source: STMicroelectronics Capital Markets Day 2024

On track to recover historical market share



#1 GP MCU market share 2021-2025

Sources: ST based on WSTS, Omdia

Doubling down on automotive MCUs

ST objective

Grow automotive MCU revenue 2x 2030 vs. 2024

How we achieve this

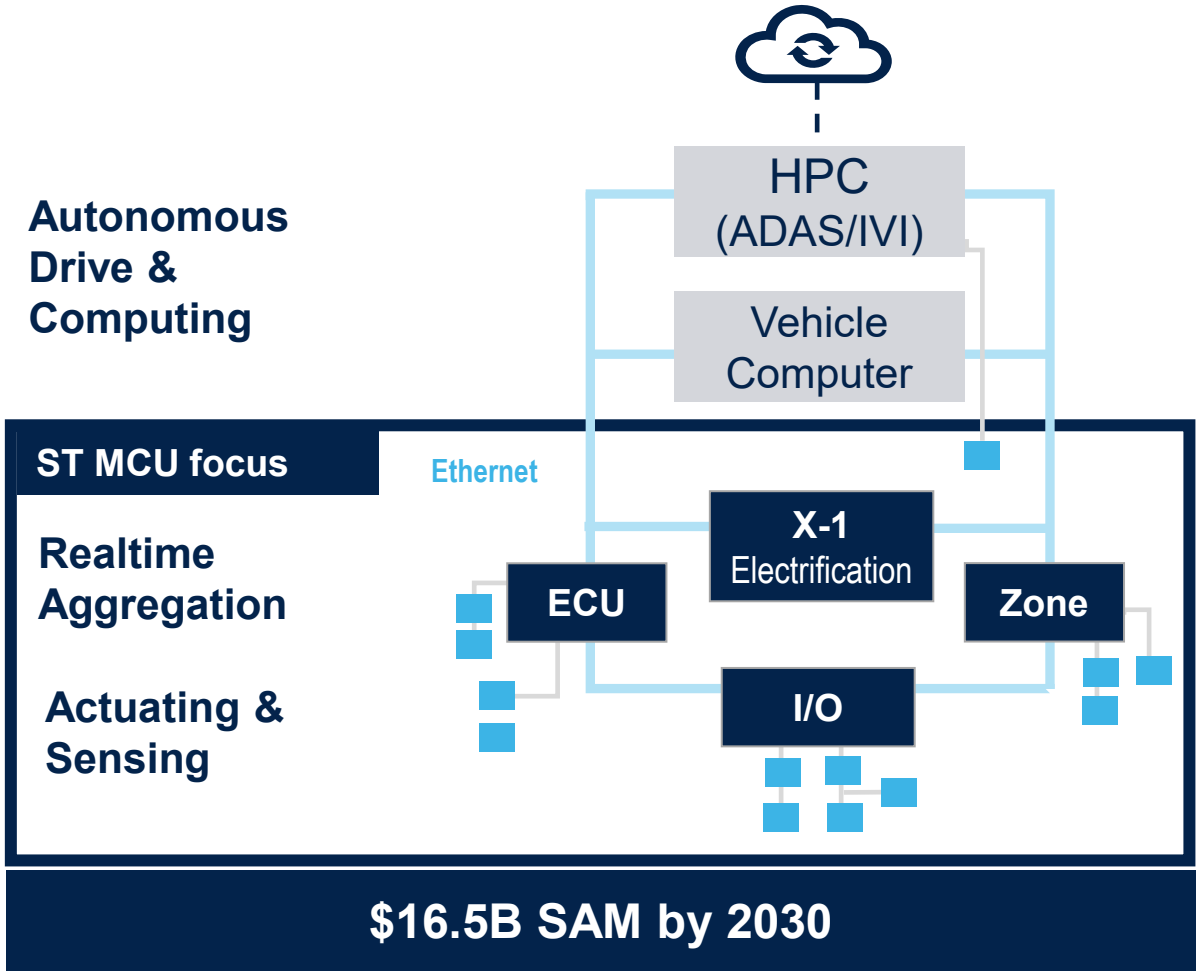
Leveraging ST's **IDM model**

Capitalizing on **ST proprietary eNVM technology**

Introducing a new class of architecture with **Stellar**

Introducing **STM32** into the automotive space

Bringing to market more than **70 commercial part numbers** to market over the next 3 years



ECU = Electronic Control Unit
ADAS = Advanced Driver Assistance Systems
IVI = In Vehicle Infotainment

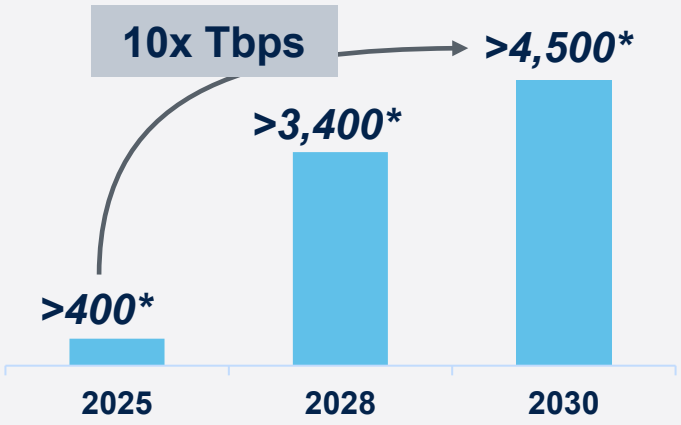
Source: S&P Q3 2024

Source: STMicroelectronics Capital Markets Day 2024

Explosive growth in LEO satellite communications ecosystem

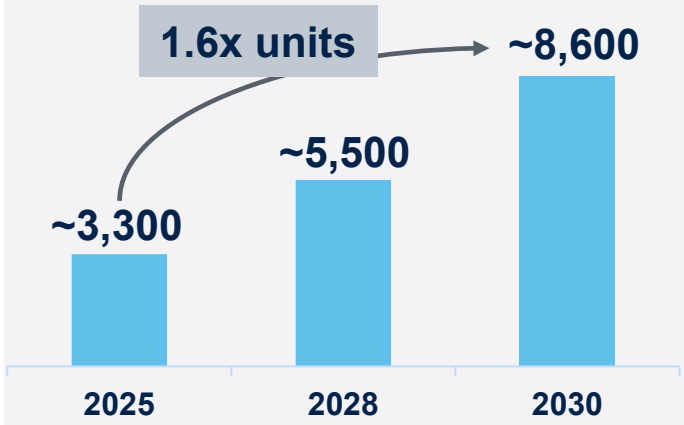
Tbps deployed in space (downlink)

Disruption in capacity created by latest launcher generation



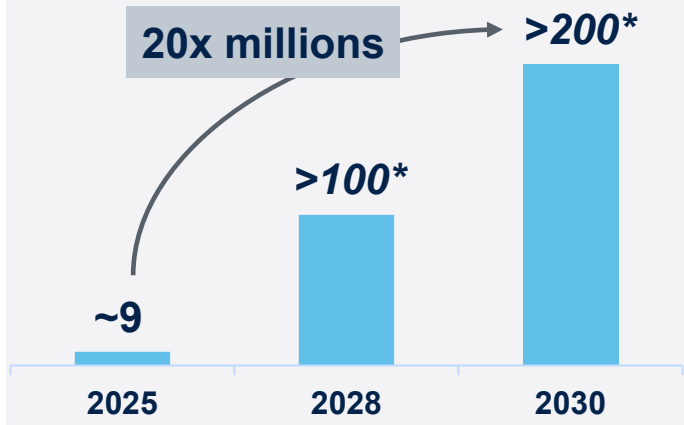
Gateways

Backhaul infrastructure growing linked to area coverage



Millions of LEO subscribers

Exponential growth fueled by new entrants



Source: Yole, Market and Technology Trends
** Source: ST internal model*

Why ST technology dominates LEO

Technology enabler for ASIC & MCU

FD-SOI

► 300 mm wafer for high-volume FD-SOI



- **FD-SOI high-performance architecture**
  Energy efficiency and radiation-capable
- **Embedded PCM NVM**
  Robust, high-temperature operation
- **Proven in orbit**
  Used by Starlink for mini laser inter-satellite

Rad-capable & high-performance technology at optimal cost

The winning combo for LEO user terminal front-end module

BiCMOS

► 200 mm wafer for high-volume B9MW
► 300 mm wafer for leading-edge B55X



- **mmW frequencies**
  Unbeatable performances from K to V band
- **Ultra-low noise**
  Large bandwidth for more users
- **High gain, low BoM**
  Cost competitive UT for end users

Best Noise Figure (NF) for RF FEMs

PLP

► Very high-volume panel-level packaging
► Versatile packaging



- **Fast volume enablement**
  up to 9M units per day
- **Unique packaging versatility**
  CSP, QFN, multi-dice in one line
- **Application friendly**
  RF high perf & power cooling

Best cost trade-off for high volume RF FEMs

ST fuels innovation with Starlink



*"The **STM32V8**'s high computing performance and integration of large embedded memory and digital features were critical in meeting our demanding real-time processing requirements, while providing a higher level of reliability and robustness to Low Earth Orbit environment, thanks to the **18nm FD-SOI technology**."*

Michael Nicolls, Vice President, Starlink Engineering at SpaceX

*"ST's **BiCMOS technology** has been a key differentiator enabling Starlink User terminal development. The technology has allowed us to build most power and area optimized RF Front end modules."*

Deepak Bansal, Head of Silicon, Starlink

*"ST's innovative **panel-level packaging technology** has been an impressive enabler to the Starlink program. This technology offers the most cost-effective low impedance interconnect at scale, ensuring the best RF performance in a high-volume fan-out package."*

John Federspiel, Head of User Terminal Engineering, Starlink

ST’s Space business ambition

Major disruption for space is driving LEO explosive growth

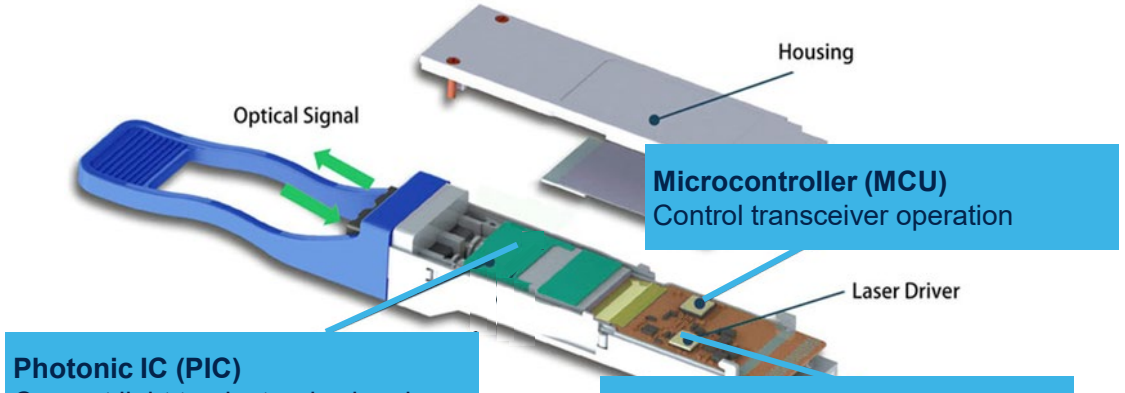


- ST’s manufacturing independence and unique technologies for Space
- A differentiated portfolio spanning every LEO layer
- LEO SAM: ~$3B by 2030, 4x vs 2025
- $3B+ space cumulative revenue in 2026–28, leading Space semis
- Orbital data center opportunity not yet factored in

A more detailed view of cloud-optical interconnect products

Pluggable

Courtesy Innolight

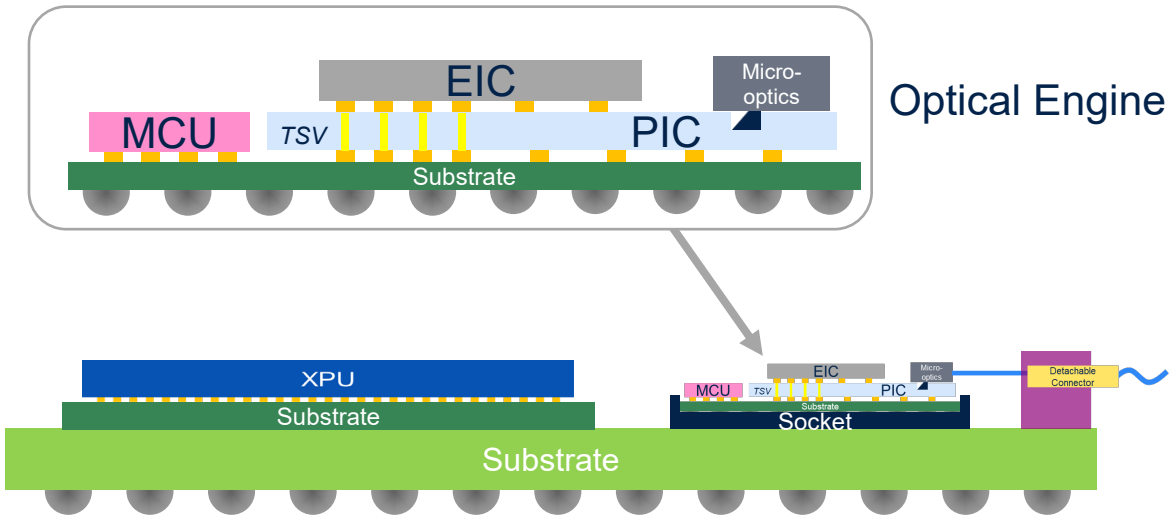


Microcontroller (MCU)
Control transceiver operation

Photonic IC (PIC)
Convert light to electronic signal

Electronic IC (EIC)
Drive laser and amplify signal

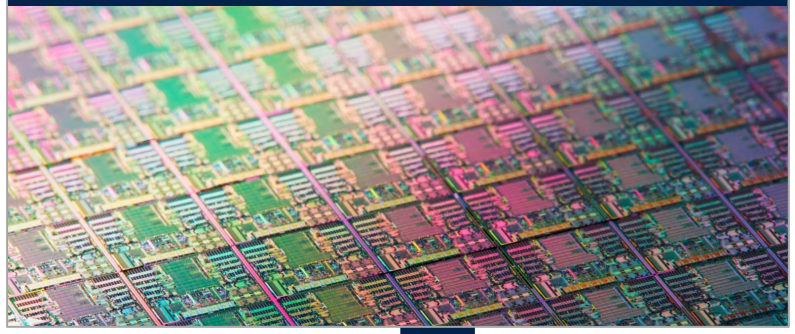
Near-packaged optics (NPO) Co-packaged optics (CPO)



ST technology integrated in advanced packaging

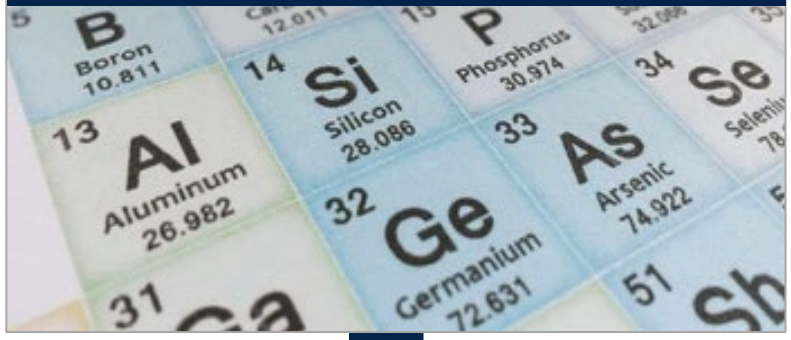
Silicon photonics for PIC

Unique silicon-only 300mm technology supporting 200G/lane



BiCMOS B55X for EIC

The high-performing 300mm BiCMOS leading RF & optical markets

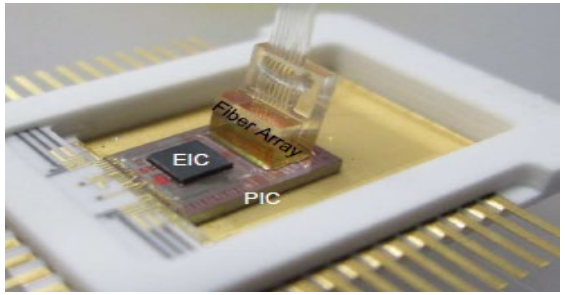


STM32 for MCU

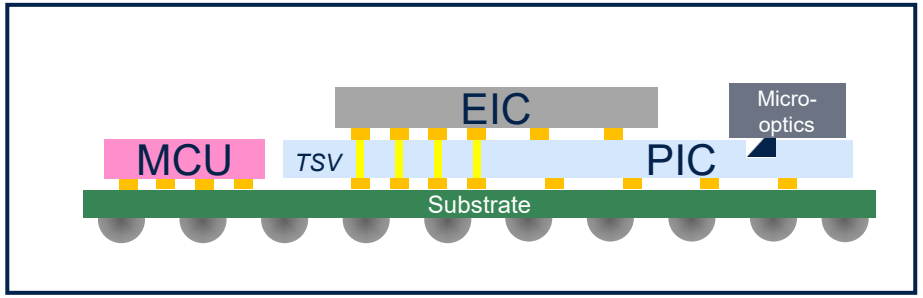
The world's leading MCU platform



Optical Engine in Advanced Packaging technology



ST provides a codesign environment, dedicated compact modulators, integration support, TSV options, bumping, packaging, and testing for **Optical Engine (OE)**



ST’s industry-leading silicon photonics platform supports AI infrastructure demand

PIC100 in 300mm high-volume production for leading hyperscalers, 4x capacity expansion by 2027

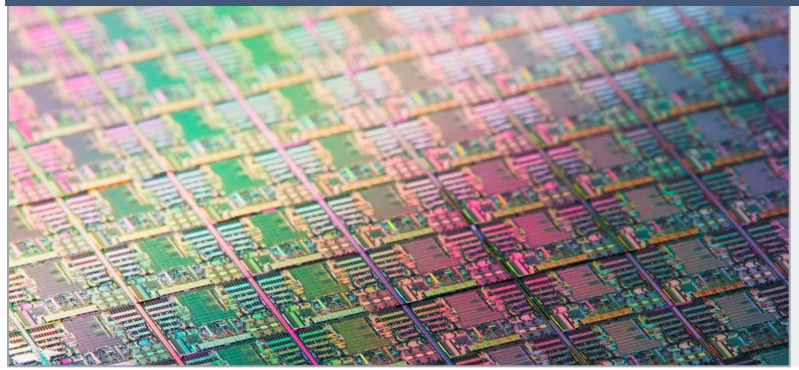
High-volume production for **silicon photonics-based PIC100** platform for optical interconnects for data centers and AI clusters

4x planned capacity expansion by 2027, further expansion in 2028. Fully **underpinned by customers’** long-term capacity reservation commitments

ST provides hyperscalers with **secure, long-term supply, predictable quality, and manufacturing resilience.**



PIC100 TSV platform to support near packaged optics (NPO) and co-packaged optics (CPO)



Next step in silicon photonics roadmap: **PIC100 TSV** to further increase optical connectivity density, module integration, and system-level thermal efficiency

PIC100 TSV is designed for **future generations of near packaged optics (NPO) and co-packaged optics (CPO),** aligning with hyperscalers’ long-term migration paths toward deeper optical–electronic integration for scale up

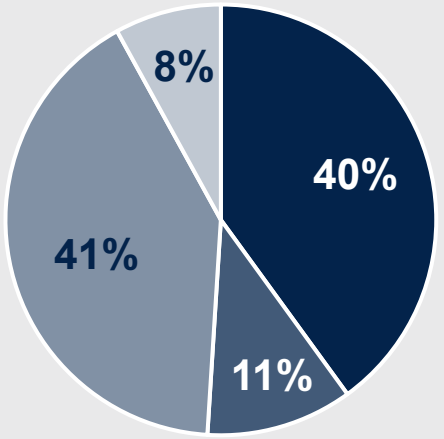
Our technology starts with You

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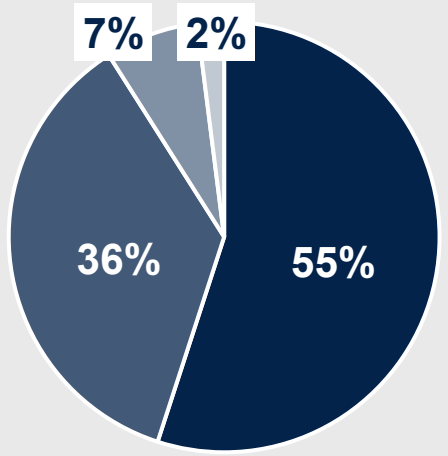
Appendix

FY 2025 Reportable segment revenues by end market

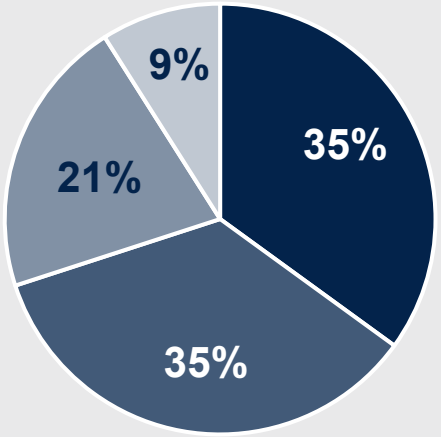
Analog products, MEMS and Sensors (AM&S)



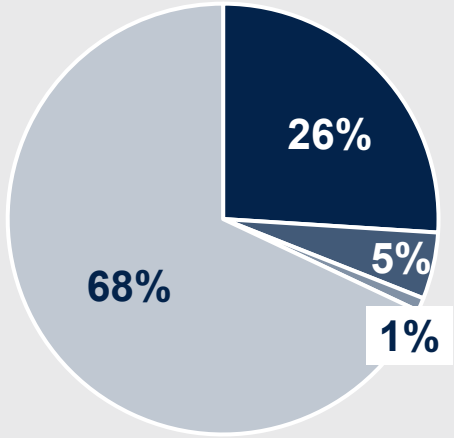
Power and discrete products (P&D)



Embedded Processing (EMP)



RF & Optical Communications (RF&OC)



- Automotive
- Industrial
- Personal electronics
- Communications equipment & computer peripherals

Historical financial performance

Effective Exchange Rate €/$	1.06	1.09	1.14	1.14	1.11	1.16	1.16
U.S. GAAP *US$M, except EPS*	**Q125**	**Q225**	**Q325**	**Q425**	**FY25**	**Q126**	**Q226**
Net Revenues	2,517	2,766	3,187	3,329	11,800	3,095	3,487
Gross Margin	33.4%	33.5%	33.2%	35.2%	33.9%	33.8%	34.8%
Operating Income Operating Margin	3 0.1%	(133) -4.8%	180 5.6%	125 3.8%	175 1.5%	70 2.3%	187 5.4%
Net Income	56	(97)	237	(30)	166	37	222
EPS Diluted ($/share)	0.06	(0.11)	0.26	(0.03)	0.18	0.04	0.24
Non-U.S. GAAP* *US$M, except EPS*	**Q125**	**Q225**	**Q325**	**Q425**	**FY25**	**Q126**	**Q226**
Gross Margin	33.4%	33.5%	33.2%	35.2%	33.9%	34.1%	35.2%
Operating Income Operating Margin	11 0.4%	57 2.1%	217 6.8%	266 8.0%	551 4.7%	171 5.5%	269 7.7%
Net Income	63	57	267	100	486	122	291
EPS Diluted ($/share)	0.07	0.06	0.29	0.11	0.53	0.13	0.31
Free Cash Flow	30	(152)	130	257	265	(723)***	75
Net Financial Position	3,082**	2,672**	2,610**	2,789**	2,789**	2,002**	2,007**

*__Non-U.S. GAAP measure__. See Appendix for additional information explaining why the Company believes these measures are important.
**__Adjusted net financial position__, taking into consideration the effect on total liquidity of advances from capital grants for which capital expenditures have not been incurred yet, stood at $2,705M in Q125, $2,311M in Q225, $2,265 in Q325, $2,456 in Q425, $1,686M in Q126 and $1,701M in Q226
***__Q126 Free cash flow__ includes $895 million cash-out related to the acquisition of NXP MEMS sensor business.

Historical Revenues and Operating Margin by Product Groups and Reportable Segments

US$M	Q125	Q225	Q325	Q425	FY25	Q126	Q226
Analog products, MEMS and Sensors (AM&S)							
Revenue	1,069	*1,133*	*1,434*	*1,449*	*5,085*	1,318	1,426
Operating Margin	*7.7%*	*7.5%*	*15.4%*	*16.2%*	*12.3%*	*12.2%*	*10.1%*
Power and discrete products (P&D)							
Revenue	397	*447*	*429*	*412*	*1,685*	389	464
Operating Margin	*-6.9%*	*-12.5%*	*-15.6%*	*-30.2%*	*-16.3%*	*-21.5%*	*-21.4%*
Analog, Power & Discrete, MEMS and Sensors (APMS)							
Revenue	**1,466**	***1,580***	***1,863***	***1,861***	***6,770***	**1,707**	**1,890**
Operating Margin	***3.7%***	***1.9%***	***8.3%***	***5.9%***	***5.1%***	***4.5%***	***2.4%***
Embedded Processing (EMP)							
Revenue	*742*	*847*	*976*	*1,015*	*3,580*	975	1,147
Operating Margin	*8.9%*	*13.5%*	*16.5%*	*19.2%*	*15.0%*	*16.9%*	*19.7%*
RF & Optical Communications (RF&OC)							
Revenue	306	*336*	*345*	*449*	*1,436*	409	445
Operating Margin	*13.9%*	*17.9%*	*16.6%*	*23.4%*	*18.5%*	*14.9%*	*21.2%*
Microcontrollers, Digital ICs and RF products (MDRF)							
Revenue	**1,048**	***1,183***	***1,321***	***1,464***	***5,016***	**1,384**	**1,592**
Operating Margin	***10.4%***	***14.8%***	***16.5%***	***20.5%***	***16.0%***	***16.3%***	***20.1%***

Appendix

- **Net financial position and Adjusted Net Financial Position (non-U.S. GAAP measure)**: represents the difference between our total liquidity and our total financial debt. Our total liquidity includes cash and cash equivalents, restricted cash, if any, short-term deposits, and marketable securities, and our total financial debt includes short-term debt and long-term debt, as reported in our Consolidated Balance Sheets. ST also presents adjusted net financial position as a non-U.S. GAAP measure, to take into consideration the effect on total liquidity of advances received on capital grants for which capital expenditures have not been incurred yet. ST believes its Net Financial Position and Adjusted Net Financial Position provide useful information for investors and management because they give evidence of our global position either in terms of net indebtedness or net cash by measuring our capital resources based on cash and cash equivalents, restricted cash, if any, short-term deposits and marketable securities and the total level of our financial debt. Our definitions of Net Financial Position and Adjusted Net Financial Position may differ from definitions used by other companies, and therefore, comparability may be limited.
- **Net Capex and Free Cash Flow (non-U.S. GAAP measure):**. ST presents Net Capex as a non-U.S. GAAP measure, which is reported as part of our Free Cash Flow (non-U.S. GAAP measure), to take into consideration the effect of advances from capital grants received on prior periods allocated to property, plant and equipment in the reporting period. Net Capex, a non-U.S. GAAP measure, is defined as (i) Payment for purchase of tangible assets, as reported plus (ii) Proceeds from sale of tangible assets, as reported plus (iii) Proceeds from capital grants and other contributions, as reported plus (iv) Advances from capital grants allocated to property, plant and equipment in the reporting period. ST believes Net Capex provides useful information for investors and management because annual capital expenditures budget includes the effect of capital grants. Our definition of Net Capex may differ from definitions used by other companies. Free Cash Flow, which is a non-U.S. GAAP measure, is defined as (i) net cash from operating activities plus (ii) Net Capex plus (iii) payment for purchase (and proceeds from sale) of intangible and financial assets and (iv) net cash paid for business acquisitions, if any. ST believes Free Cash Flow provides useful information for investors and management because it measures our capacity to generate cash from our operating and investing activities to sustain our operations. Free Cash Flow reconciles with the total cash flow and the net cash increase (decrease) by including the payment for purchases of (and proceeds from matured) marketable securities and net investment in (and proceeds from) short-term deposits, the net cash from (used in) financing activities and the effect of changes in exchange rates, and by excluding the advances from capital grants received on prior periods allocated to property, plant and equipment in the reporting period. Our definition of Free Cash Flow may differ from definitions used by other companies..
- **Net revenues of Others:** include revenues from sales assembly services and other revenues. Operating income (loss) of Others include items such as unused capacity charges, including incidents leading to power outage, impairment, restructuring charges and other related phase-out costs, management reorganization costs, start-up costs, and other unallocated income (expenses) such as: strategic or special research and development programs, certain corporate-level operating expenses, patent claims and litigations, and other costs that are not allocated to reportable segments, operating earnings of other products as well as Purchase Price Allocation (PPA) effects from the acquisition of NXP's MEMS sensor business. With additional cost elements included in the table below::

US$M	Q125	Q225	Q325	Q425	FY25	Q126	Q226
Unused Capacity Charges	123	103	102	88	416	69	37
Impairment, restructuring charges and other related phase-out costs	8	190	37	141	376	71	58
PPA effects from the acquisition of NXP's MEMS sensor business	-	-	-	-	-	30	24